

Kinetis KM35 Sub-Family Data Sheet

Enabling high accuracy, secure 1-, 2- and 3-phase electricity metering solutions through a powerful analog front end (AFE), auto-compensated iRTC with hardware tamper detection, segment LCD controller, rich security protection and multiple low power features in a 32-bit Arm® Cortex®-M0+ MCU. This product offers:

- Enabling single-chip 1-, 2- and 3-phase metering designs
 - AFE, Security and HMI. Single crystal implementation
 - Single point of calibration during manufacture
- Highest accuracy metrology with regional feature support
 - Multiple $\Sigma\Delta$ ADCs with PGA
 - Supports neutral disconnect use case
- Compliance with WELMEC/OIML recommendations
 - Memory and peripheral protection
 - Hardware tamper detect with time stamping
 - Low-power RTC, battery backup with tamper memory

Core

- Arm® Cortex®-M0+ core up to 75 MHz
- Metering specific Memory Mapped Arithmetic Unit (MMAU)

Clocks

- 75 MHz high-accuracy internal reference clock
- 32 kHz, and 4 MHz internal reference clock
- 1 kHz LPO clock
- 32.768 kHz crystal oscillator in iRTC power domain
- 1 MHz to 32 MHz crystal oscillator
- FLL and PLL

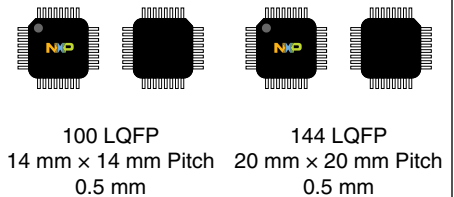
System peripherals

- Memory Protection Unit (MPU)
- 4-channel DMA controller
- Watchdog and EWM
- Low-leakage Wakeup Unit (LLWU)
- SWD debug interface and Micro Trace Buffer (MTB)
- Bit Manipulation Engine (BME)
- Inter-peripheral Crossbar Switch (XBAR)

Analog Modules

- 4 AFE channels (4x 24-bit $\Sigma\Delta$ ADCs with PGA)
- 16-channel 16-bit SAR ADC with 4 result registers
- High-speed analog comparator containing a 6-bit DAC and programmable reference input
- Internal 1.2 V reference voltage 10–15 ppm/°C

MKM35Z256VLL7
MKM35Z256VLQ7
MKM35Z512VLL7
MKM35Z512VLQ7



Memories

- Up to 512 KB program flash memory
- Up to 64 KB SRAM

Operating Characteristics

- Voltage range: 1.71 to 3.6 V (without AFE)
- Voltage range: 2.7 to 3.6 V (with AFE)
- Temperature range (ambient): –40 to 105 °C

Low power features

- 13 power modes to provide power optimization based on application requirements
- 8.82 mA @ 75 MHz run current
- Less than 220 μ A very low power run current
- 6.05 μ A very low power stop current
- Down to 261 nA deep sleep current
- V_{BAT} domain current < 1 μ A with iRTC operational
- Low-power boot with less than 2.33 mA peak current

Communication interfaces

- 16-bit SPI modules
- Low-power UART module
- UART module complying with ISO7816-3
- Basic UART module
- I²C with SMBus

Timers

- Quad Timer (QTMR)
- Periodic Interrupt Timer (PIT)
- Low Power Timer (LPTMR)
- Programmable Delay Block (PDB)
- Independent Real Time Clock (iRTC)

Human-machine interface

- Up to 4x60 (8x56, 6x58) segment LCD controller operating in all low-power modes
- General purpose input/output (GPIO)

Security and integrity modules

- Memory Mapped Cryptographic Acceleration Unit (MMCAU) for AES encryption
- Random Number Generator (RNGA), complying with NIST: SP800-90
- Programmable Cyclic Redundancy Check (PCRC)
- 80-bit unique identification number per chip

The following figure shows the functional modules in the chip.

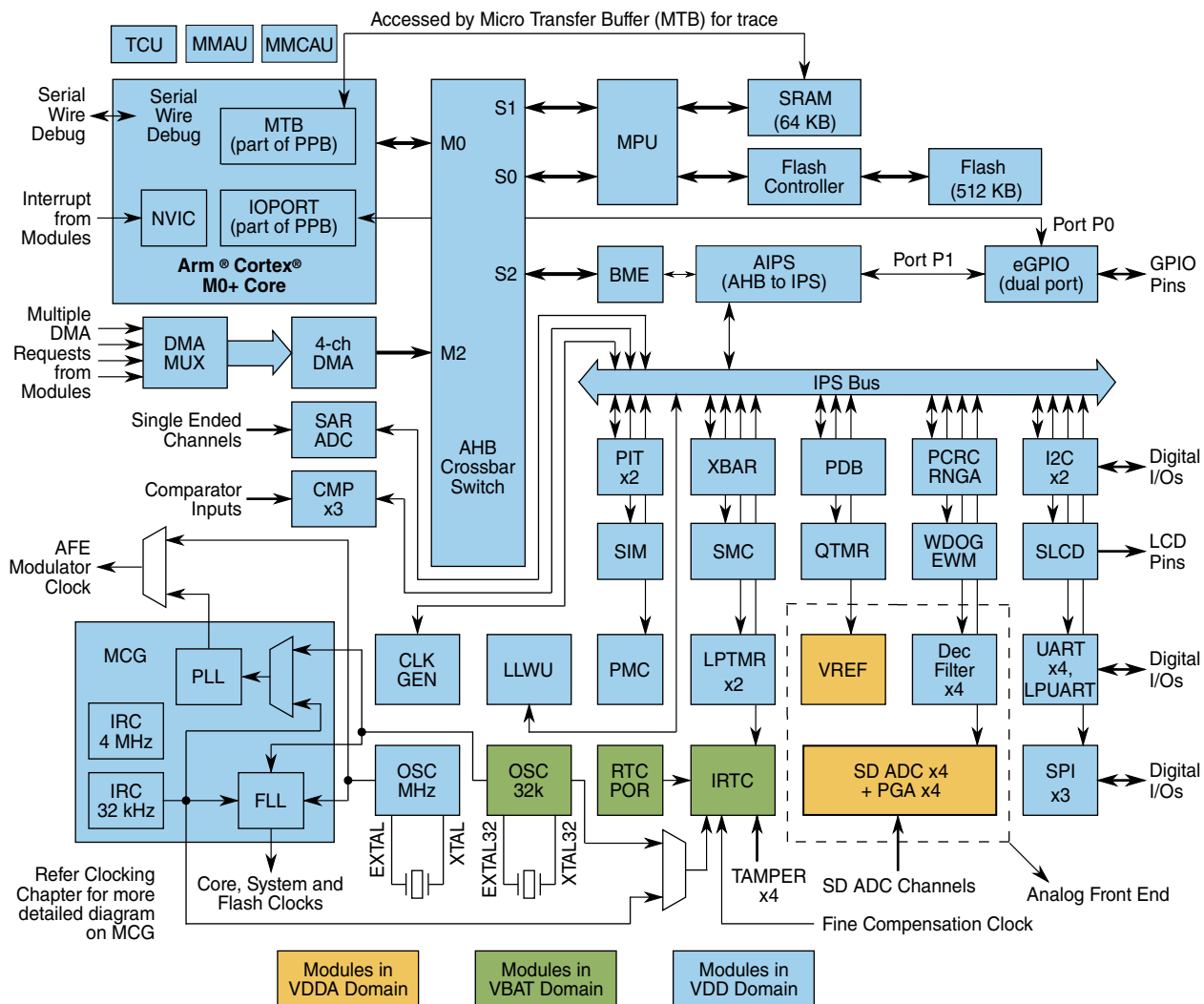


Figure 1. Functional block diagram

Ordering Information

Part Number ¹	Memory		ADC Channels	Maximum number of GPIOs	Security	SLCD	Package Type	Packaging Type
	Flash (KB)	SRAM (KB)						
MKM35Z256VLL7	256	64	12	72	CRC, MMCAU, RNG	Yes	LQFP 100	Tray
MKM35Z256VLQ7	256	64	16	99	CRC, MMCAU, RNG	Yes	LQFP 144	Tray
MKM35Z256VLL7R	256	64	12	72	CRC, MMCAU, RNG	Yes	LQFP 100	Reel
MKM35Z256VLQ7R	256	64	16	99	CRC, MMCAU, RNG	Yes	LQFP 144	Reel
MKM35Z512VLL7	512	64	12	72	CRC, MMCAU, RNG	Yes	LQFP 100	Tray
MKM35Z512VLQ7	512	64	16	99	CRC, MMCAU, RNG	Yes	LQFP 144	Tray
MKM35Z512VLL7R	512	64	12	72	CRC, MMCAU, RNG	Yes	LQFP 100	Reel
MKM35Z512VLQ7R	512	64	16	99	CRC, MMCAU, RNG	Yes	LQFP 144	Reel

1. To confirm current availability of orderable part numbers, go to <http://www.nxp.com> and perform a part number search.

Related Resources

Type	Description	Resource
Selector Guide	The NXP Solution Advisor is a web-based tool that features interactive application wizards and a dynamic product selector.	Solution Advisor
Product Brief	The Product Brief contains concise overview/summary information to enable quick evaluation of a device for design suitability.	KM3xPB ¹
Reference Manual	The Reference Manual contains a comprehensive description of the structure and function (operation) of a device.	KM35P144M75SF0RM
Data Sheet	The Data Sheet includes electrical characteristics and signal connections.	This document: KM35P144M75SF0
Chip Errata	The chip mask set Errata provides additional or corrective information for a particular device mask set.	KINETIS_M_P90A
Package Drawing	Package dimensions are provided in package drawings.	100-LQFP: 98ASS23308W ¹ 144-LQFP: 98ASS23177W ¹

1. To find the associated resource, go to <http://www.nxp.com> and perform a search using this term.

Table of Contents

1	Ratings.....	5	3.4.3	Voltage reference electrical specifications.....	30
1.1	Thermal handling ratings.....	5	3.4.4	AFE electrical specifications.....	31
1.2	Moisture handling ratings.....	5	3.5	Timers.....	35
1.3	ESD handling ratings.....	5	3.6	Communication interfaces.....	35
1.4	Voltage and current operating ratings.....	6	3.6.1	I2C switching specifications.....	35
2	General.....	6	3.6.2	UART switching specifications.....	36
2.1	AC electrical characteristics.....	6	3.6.3	SPI switching specifications.....	36
2.2	Nonswitching electrical specifications.....	6	3.7	Human-Machine Interfaces (HMI).....	40
2.2.1	Voltage and current operating requirements.....	6	3.7.1	LCD electrical characteristics.....	40
2.2.2	LVD and POR operating requirements.....	7	4	Dimensions.....	42
2.2.3	Voltage and current operating behaviors.....	8	4.1	Obtaining package dimensions.....	42
2.2.4	Power mode transition operating behaviors.....	9	5	Pinout.....	42
2.2.5	Power consumption operating behaviors.....	10	5.1	KM35 Signal multiplexing and pin assignments.....	42
2.2.6	Designing with radiated emissions in mind.....	12	5.2	KM35 Pinouts.....	50
2.2.7	Capacitance attributes.....	12	6	Ordering parts.....	51
2.3	Switching specifications.....	12	6.1	Determining valid orderable parts.....	51
2.3.1	Device clock specifications.....	12	7	Part identification.....	52
2.3.2	General switching specifications.....	13	7.1	Description.....	52
2.4	Thermal specifications.....	14	7.2	Format.....	52
2.4.1	Thermal operating requirements.....	14	7.3	Fields.....	52
2.4.2	Thermal attributes.....	14	7.4	Example.....	53
3	Peripheral operating requirements and behaviors.....	14	8	Terminology and guidelines.....	53
3.1	Core modules.....	14	8.1	Definition: Operating requirement.....	53
3.1.1	Single Wire Debug (SWD).....	14	8.2	Definition: Operating behavior.....	53
3.1.2	Analog Front End (AFE).....	15	8.3	Definition: Attribute.....	54
3.2	Clock modules.....	16	8.4	Definition: Rating.....	54
3.2.1	MCG specifications.....	16	8.5	Result of exceeding a rating.....	55
3.2.2	Oscillator electrical specifications.....	18	8.6	Relationship between ratings and operating requirements.....	55
3.2.3	32 kHz oscillator electrical characteristics.....	21	8.7	Guidelines for ratings and operating requirements.....	55
3.3	Memories and memory interfaces.....	23	8.8	Definition: Typical value.....	56
3.3.1	Flash electrical specifications.....	23	8.9	Typical value conditions.....	57
3.4	Analog.....	24	9	Revision History.....	57
3.4.1	ADC electrical specifications.....	24			
3.4.2	CMP and 6-bit DAC electrical specifications.....	28			

1 Ratings

1.1 Thermal handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
T _{STG}	Storage temperature	-55	150	°C	1
T _{SDR}	Solder temperature, lead-free	—	260	°C	2

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

1.2 Moisture handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
MSL	Moisture sensitivity level	—	3	—	1

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

1.3 ESD handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
V _{HBM}	Electrostatic discharge voltage, human body model (All pins except RESET pin)	-4000	+4000	V	
	Electrostatic discharge voltage, human body model (RESET pin only)	-2500	+2500	V	1
V _{CDM}	Electrostatic discharge voltage, charged-device model (for corner pins)	-750	+750	V	
V _{CDM}	Electrostatic discharge voltage, charged-device model	-500	+500	V	2
I _{LAT}	Latch-up current at ambient temperature of 105 °C	-100	+100	mA	

1. Determined according to JEDEC Standard JS-001-2014, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JS-001-2014, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.

1.4 Voltage and current operating ratings

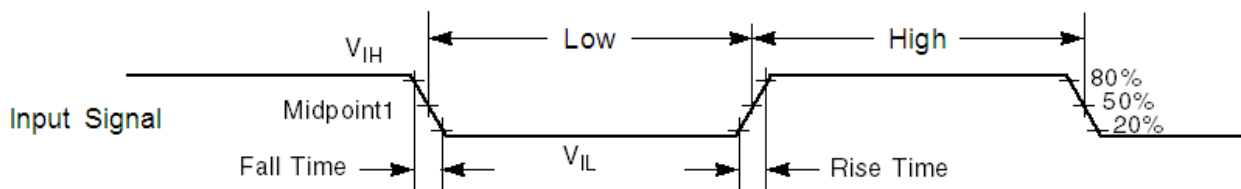
Symbol	Description	Min.	Max.	Unit
V_{DD}	Digital supply voltage	-0.3	3.6	V
V_{DIO}	Digital input voltage (except \overline{RESET} , EXTAL, and XTAL)	-0.3	$V_{DD} + 0.3$	V
$V_{DTamper}$	Tamper input voltage	-0.3	$V_{BAT} + 0.3$	V
V_{AIO}	Analog ¹ , \overline{RESET} , EXTAL, and XTAL input voltage	-0.3	$V_{DD} + 0.3$	V
I_D	Instantaneous maximum current single pin limit (applies to all port pins)	-25	25	mA
V_{DDA}	Analog supply voltage	$V_{DD} - 0.3$	$V_{DD} + 0.3$	V
V_{BAT}	RTC battery supply voltage	-0.3	3.6	V

1. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

2 General

2.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.



The midpoint is $V_{IL} + (V_{IH} - V_{IL})/2$.

Figure 2. Input signal measurement reference

2.2 Nonswitching electrical specifications

2.2.1 Voltage and current operating requirements

Table 1. Voltage and current operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V _{DD}	Supply voltage when AFE is operational	2.7	3.6	V	
	Supply voltage when AFE is NOT operational	1.71	3.6	V	
V _{DDA}	Analog supply voltage	2.7	3.6	V	
V _{DD} – V _{DDA}	V _{DD} -to-V _{DDA} differential voltage	–0.1	0.1	V	
V _{SS} – V _{SSA}	V _{SS} -to-V _{SSA} differential voltage	–0.1	0.1	V	
V _{BAT}	RTC battery supply voltage	1.71	3.6	V	1
V _{IH}	Input high voltage <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V 	0.7 × V _{DD}	—	V	
		0.75 × V _{DD}	—	V	
V _{IL}	Input low voltage <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V 	—	0.35 × V _{DD}	V	
		—	0.3 × V _{DD}	V	
V _{HYS}	Input hysteresis	0.06 × V _{DD}	—	V	
I _{ICDIO}	Digital pin negative DC injection current — single pin <ul style="list-style-type: none"> • V_{IN} < V_{SS}–0.3 V 	–5	—	mA	
I _{ICAIO}	Analog ² , EXTAL, and XTAL pin DC injection current — single pin <ul style="list-style-type: none"> • V_{IN} < V_{SS}–0.3 V (Negative current injection) • V_{IN} > V_{DD}+0.3 V (Positive current injection) 	–3	—	mA	
		—	+3	mA	
I _{ICcont}	Contiguous pin DC injection current —regional limit, includes sum of negative injection currents or sum of positive injection currents of 16 contiguous pins <ul style="list-style-type: none"> • Negative current injection • Positive current injection 	–25	—	mA	
		—	+25	mA	
V _{RFVBAT}	V _{BAT} voltage required to retain the VBAT register file	V _{POR_VBAT}	—	V	

1. V_{BAT} always needs to be there for the chip to be operational.
2. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

2.2.2 LVD and POR operating requirements

Table 2. V_{DD} supply LVD and POR operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{POR}	Falling VDD POR detect voltage	0.8	1.1	1.5	V	

Table continues on the next page...

Table 2. V_{DD} supply LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{LVDH}	Falling low-voltage detect threshold — high range (LVDV=01)	2.48	2.56	2.64	V	
V _{LVW1H}	Low-voltage warning thresholds — high range					1
	• Level 1 falling (LVWV=00)	2.62	2.70	2.78	V	
V _{LVW2H}	• Level 2 falling (LVWV=01)	2.72	2.80	2.88	V	
V _{LVW3H}	• Level 3 falling (LVWV=10)	2.82	2.90	2.98	V	
V _{LVW4H}	• Level 4 falling (LVWV=11)	2.92	3.00	3.08	V	
V _{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	80	—	mV	
V _{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	
V _{LVW1L}	Low-voltage warning thresholds — low range					1
	• Level 1 falling (LVWV=00)	1.74	1.80	1.86	V	
V _{LVW2L}	• Level 2 falling (LVWV=01)	1.84	1.90	1.96	V	
V _{LVW3L}	• Level 3 falling (LVWV=10)	1.94	2.00	2.06	V	
V _{LVW4L}	• Level 4 falling (LVWV=11)	2.04	2.10	2.16	V	
V _{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	60	—	mV	
V _{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	
t _{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	μs	

1. Rising threshold is the sum of falling threshold and hysteresis voltage.

Table 3. VBAT power operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{POR_VBAT}	Falling VBAT supply POR detect voltage	0.8	1.1	1.5	V	

2.2.3 Voltage and current operating behaviors

Table 4. Voltage and current operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
V _{OH}	Output high voltage — low-drive strength				
	• 2.7 V ≤ V _{DD} ≤ 3.6 V, I _{OH} = 5 mA	V _{DD} - 0.5	—	V	
	• 1.71 V ≤ V _{DD} ≤ 2.7 V, I _{OH} = 2.5 mA	V _{DD} - 0.5	—	V	
I _{OHT}	Output high current total for all ports	—	100	mA	

Table continues on the next page...

Table 4. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Max.	Unit	Notes
V _{OL}	Output low voltage — low-drive strength <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 5 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 2.5 mA 	—	0.5	V	
		—	0.5	V	
I _{OLT}	Output low current total for all ports	—	100	mA	
I _{OZ}	Hi-Z (off-state) leakage current (per pin)	—	1	μA	
R _{PU}	Internal pull-up resistors	30	60	kΩ	1
R _{PD}	Internal pull-down resistors	30	60	kΩ	2

1. Measured at V_{input} = V_{SS}.
2. Measured at V_{input} = V_{DD}.

2.2.4 Power mode transition operating behaviors

All specifications except t_{POR}, and VLLS_x→RUN recovery times in the following table assume this clock configuration:

- CPU and system clocks = 75 MHz
- Bus clock = 25 MHz
- Flash clock = 25 MHz
- Temperature: -40 °C, 25 °C, and 105 °C
- V_{DD}: 1.71 V, 3.3 V, and 3.6 V

Table 5. Power mode transition operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t _{POR}	After a POR event, amount of time from the point V _{DD} reaches 1.71 V to execute the first instruction across the operating temperature range of the chip.	563		659	μs	1
	• VLLS0 → RUN	—	370	382	μs	
	• VLLS1 → RUN	—	370	382	μs	
	• VLLS2 → RUN	—	270	275	μs	
	• VLLS3 → RUN	—	270	275	μs	
	• VLPS → RUN	—	5	6	μs	
	• STOP → RUN	—	5	6	μs	

General

1. Normal boot (FTFA_OPT[LPBOOT]=1)

2.2.5 Power consumption operating behaviors

NOTE

The maximum (Max.) values stated in the following table represent characterized results equivalent to the mean plus three times the standard deviation (mean + 3×sigma).

Table 6. Power consumption operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I _{DDA}	Analog supply current	—	—	See note	mA	1
I _{DD_RUN}	Run mode current — all peripheral clocks disabled, code executing from flash <ul style="list-style-type: none"> • @ 3.0 V • 25 °C • -40 °C • 105 °C 	—	8.82	9.15	mA	2
		—	8.80	9.13	mA	
		—	9.19	9.59	mA	
		—	—	—	—	
I _{DD_RUN}	Run mode current — all peripheral clocks enabled, code executing from flash <ul style="list-style-type: none"> • @ 3.0 V • 25 °C • -40 °C • 105 °C 	—	12.38	12.83	mA	2
		—	12.32	12.76	mA	
		—	12.67	13.1	mA	
		—	—	—	—	
I _{DD_WAIT}	Wait mode high frequency current at 3.0 V— all peripheral clocks disabled and Flash is not in low-power <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	5.78	5.90	mA	2
		—	5.76	5.88	mA	
		—	6.34	6.52	mA	
		—	—	—	—	
I _{DD_WAIT}	Wait mode high frequency current at 3.0 V— all peripheral clocks disabled and Flash disabled (put in low-power) <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	4.56	4.6	mA	2
		—	4.56	4.68	mA	
		—	4.98	5.15	mA	
		—	—	—	—	
I _{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks disabled <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	212	500	μA	3
		—	212	470	μA	
		—	550	900	μA	
		—	—	—	—	
I _{DD_VLPR}	Very-low-power run mode current at 3.0 V — all peripheral clocks enabled <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	343	530	μA	4
		—	327	507	μA	
		—	638	1000	μA	
		—	—	—	—	

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I _{DD_VLPW}	Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	133	350	μA	5
		—	132	330	μA	
		—	475	800	μA	
I _{DD_STOP}	Stop mode current at 3.0 V <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	406	730	μA	
		—	386	700	μA	
		—	792	898	μA	
I _{DD_VLPS}	Very-low-power stop mode current at 3.0 V <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	6.05	46	μA	
		—	2.68	44	μA	
		—	347	700	μA	
I _{DD_VLLS3}	Very low-leakage stop mode 3 current at 3.0 V <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	2.78	3.86	μA	
		—	2.16	3.85	μA	
		—	61.9	85.0	μA	
I _{DD_VLLS2}	Very low-leakage stop mode 2 current at 3.0 V <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	2.45	3.06	μA	
		—	2.10	3.04	μA	
		—	40.2	59.5	μA	
I _{DD_VLLS1}	Very low-leakage stop mode 1 current at 3.0 V <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	1.20	2.14	μA	
		—	1.07	1.84	μA	
		—	30.8	38.8	μA	
I _{DD_VLLS0}	Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit disabled <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	0.261	0.67	μA	
		—	0.222	0.64	μA	
		—	29.1	38.0	μA	
I _{DD_VLLS0}	Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit enabled <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	0.559	0.790	μA	
		—	0.494	0.784	μA	
		—	29.5	38.4	μA	
I _{DD_VBAT}	Average current with RTC and 32 kHz disabled at 3.0 V and VDD is OFF <ul style="list-style-type: none"> • 25 °C • -40 °C • 105 °C 	—	0.243	1.00	μA	
		—	0.143	0.95	μA	
		—	6.05	15	μA	

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I _{DD_VBAT}	Average current when VDD is OFF and LFSR and Tamper clocks set to 2 Hz.	—	1.42	3.00	μA	6, 7
	• @ 3.0 V		1.24	2.96	μA	
	• 25 °C		8.04	16.0	μA	
	• -40 °C					
	• 105 °C					

1. See all related analog peripheral specifications for I_{DDA}.
2. 75 MHz core and system clock, 25 MHz bus clock, and 25 MHz flash clock. MCG configured for FBE mode. All peripheral clocks disabled.
3. 2 MHz core/system clock, and 1 MHz bus/flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. Code executing while (1) loop from flash.
4. 2 MHz core/system clock, and 1 MHz bus/flash clock. MCG configured for BLPE mode. All peripheral clocks enabled but peripherals are not in active operation. Code executing while (1) loop from flash.
5. 2 MHz core/system clock, and 1 MHz bus/flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. No flash accesses; some activity on DMA & RAM assumed.
6. Includes 32 kHz oscillator current and RTC operation.
7. An external power switch for VBAT should be present on board to have better battery life and keep VBAT pin powered in all conditions. There is no internal power switch in RTC.

2.2.6 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

1. Go to www.nxp.com.
2. Perform a keyword search for “EMC design.”

2.2.7 Capacitance attributes

Table 7. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C _{IN_A}	Input capacitance: analog pins	—	7	pF
C _{IN_D}	Input capacitance: digital pins	—	7	pF
C _{IN_D_io60}	Input capacitance: fast digital pins	—	9	pF

2.3 Switching specifications

2.3.1 Device clock specifications

Table 8. Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
Normal run mode					
f _{SYS}	System and core clock	—	75	MHz	
f _{BUS}	Bus clock	—	25	MHz	
f _{FLASH}	Flash clock	—	25	MHz	
f _{AFE}	AFE Modulator clock	—	6.5	MHz	
VLPR mode ¹					
f _{SYS}	System and core clock	—	4	MHz	
f _{BUS}	Bus clock	—	1	MHz	
f _{FLASH}	Flash clock	—	1	MHz	
f _{AFE}	AFE Modulator clock ²	—	1.6	MHz	

1. The frequency limitations in VLPR mode here override any frequency specification listed in the timing specification for any other module.
2. AFE working in low-power mode.

2.3.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, and I²C signals.

Table 9. General switching specifications

Symbol	Description	Min.	Max.	Unit	Notes
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Asynchronous path	16	—	ns	
	External reset pulse width (digital glitch filter disabled)	100	—	ns	2
	Port rise and fall time <ul style="list-style-type: none"> • Slew disabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7 \text{ V}$ • $2.7 \leq V_{DD} \leq 3.6 \text{ V}$ • Slew enabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7 \text{ V}$ • $2.7 \leq V_{DD} \leq 3.6 \text{ V}$ 	—	8	ns	
		—	5	ns	
		—	27	ns	
		—	16	ns	

1. The greater synchronous and asynchronous timing must be met.
2. This is the shortest pulse that is guaranteed to be recognized.

2.4 Thermal specifications

2.4.1 Thermal operating requirements

Table 10. Thermal operating requirements

Symbol	Description	Min.	Max. ¹	Unit
T _J	Die junction temperature	-40	125	°C
T _A	Ambient temperature	-40	105	°C

1. Maximum T_A can be exceeded **only if** the user ensures that T_J does **not** exceed maximum T_J. The simplest method to determine T_J is:

$$T_J = T_A + R_{\theta JA} \times \text{chip power dissipation.}$$

2.4.2 Thermal attributes

Rating	Board Type ¹	Symbol	100 LQFP	144 LQFP	Unit
Junction to Ambient Thermal Resistance ²	JESD51-7, 2s2p	R _{θJA}	48.6	41.7	°C/W
Junction-to-Top of Package Thermal Characterization Parameter ²	JESD51-7, 2s2p	Ψ _{JT}	0.52	0.63	°C/W

1. Thermal test board meets JEDEC specification for this package (JESD51-7).
2. Determined in accordance to JEDEC JESD51-2A natural convection environment. Thermal resistance data in this report is solely for a thermal performance comparison of one package to another in a standardized specified environment. It is not meant to predict the performance of a package in an application-specific environment.

3 Peripheral operating requirements and behaviors

3.1 Core modules

3.1.1 Single Wire Debug (SWD)

Table 11. SWD switching characteristics at 2.7 V (2.7–3.6 V)

Symbol	Description	Value	Unit	Notes
SWD CLK	Frequency of SWD operation	20	MHz	
Inputs, t_{SUI}	Data setup time	5	ns	1
inputs, t_{HI}	Data hold time	0	ns	1
after clock edge, t_{DVO}	Data valid Time	32	ns	1
t_{HO}	Data Valid Hold	0	ns	1

1. Input transition assumed = 1 ns. Output transition assumed = 50 pF.

Table 12. Switching characteristics at 1.7 V (1.7–3.6 V)

Symbol	Description	Value	Unit	Notes
SWD CLK	Frequency of SWD operation	18	MHz	
Inputs, t_{SUI}	Data setup time	4.7	ns	1
inputs, t_{HI}	Data hold time	0	ns	1
after clock edge, t_{DVO}	Data valid Time	49.4	ns	2
t_{HO}	Data Valid Hold	0	ns	1

1. Input transition assumed = 1 ns. Output transition assumed = 50 pF.

2. Frequency of SWD clock (18 MHz) is applicable only in case the input setup time of the device outside is not more than 6.15 ns, else the frequency of SWD clock would need to be lowered.

3.1.2 Analog Front End (AFE)

AFE switching characteristics at (2.7 V–3.6 V)

Case 1: Clock is coming In and Data is also coming In (XBAR ports timed with respect to AFE clock defined at pad PTB7, PTE3, and PTK4).

Table 13. AFE switching characteristics (2.7 V–3.6 V)

Symbol	Description	Value	Unit	Notes
AFE CLK	Frequency of operation	10	MHz	
Inputs, t_{SUI}	Data setup time	5	ns	1
inputs, t_{HI}	Data hold time	0	ns	1

1. Input Transition: 1 ns. Output Load: 50 pF.

Case 2: Clock is going Out and Data is coming In (XBAR ports timed with respect to generated clock defined at the XBAR out ports).

Table 14. AFE switching characteristics (2.7 V–3.6 V)

Symbol	Description	Value	Unit	Notes
AFE CLK	Frequency of operation	6.2	MHz	
Inputs, t_{SUI}	Data setup time	36	ns	1
inputs, t_{HI}	Data hold time	0	ns	1

1. Input Transition: 1 ns. Output Load: 50 pF.

AFE switching characteristics at (1.7 V–3.6 V)

Case 1: Clock is coming In and Data is also coming In (XBAR ports timed with respect to AFE clock defined at pad PTB7, PTE3, and PTK4).

Table 15. AFE switching characteristics (1.7 V–3.6 V)

Symbol	Description	Value	Unit	Notes
AFE CLK	Frequency of operation	13	MHz	
Inputs, t_{SUI}	Data setup time	30	ns	1
inputs, t_{HI}	Data hold time	5	ns	1

1. Input Transition: 1 ns. Output Load: 50 pF.

Case 2: Clock is going Out and Data is coming In (XBAR ports timed with respect to generated clock defined at XBAR out ports).

Table 16. AFE switching characteristics (1.7 V–3.6 V)

Symbol	Description	Value	Unit	Notes
AFE CLK	Frequency of operation	6.5	MHz	
Inputs, t_{SUI}	Data setup time	36	ns	1
inputs, t_{HI}	Data hold time	0	ns	1

1. Input Transition: 1 ns. Output Load: 50 pF.

3.2 Clock modules

3.2.1 MCG specifications

Table 17. MCG specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes	
$f_{\text{ints_ft}}$	Internal reference frequency (slow clock) — factory trimmed at nominal V_{DD} and 25 °C	—	32.768	—	kHz		
$\Delta f_{\text{ints_t}}$	Total deviation of internal reference frequency (slow clock) over voltage and temperature	—	+0.5/-0.7	—	%		
$\Delta f_{\text{ints_t}}$	Total deviation of internal reference frequency (slow clock) over fixed voltage and full operating temperature range	-2	—	+2	%		
$f_{\text{ints_t}}$	Internal reference frequency (slow clock) — user trimmed	31.25	—	39.0625	kHz		
$\Delta f_{\text{dco_res_t}}$	Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM	—	± 0.3	± 0.6	$\%f_{\text{dco}}$		
$\Delta f_{\text{dco_t}}$	Total deviation of trimmed average DCO output frequency over voltage and temperature	—	+0.5/-0.7	—	$\%f_{\text{dco}}$	1	
$\Delta f_{\text{dco_t}}$	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70 °C	—	± 0.4	—	$\%f_{\text{dco}}$	1	
$f_{\text{intf_ft}}$	Internal reference frequency (fast clock) — factory trimmed at nominal V_{DD} and 25 °C	—	4	—	MHz		
$\Delta f_{\text{intf_t}}$	Total deviation of internal reference frequency (fast clock) over voltage and temperature — factory trimmed at nominal V_{DD} and 25 °C	—	+1/-2	—	%		
$f_{\text{intf_t}}$	Internal reference frequency (fast clock) — user trimmed at nominal V_{DD} and 25 °C	3	—	5	MHz		
$f_{\text{loc_low}}$	Loss of external clock minimum frequency — RANGE = 00	$(3/5) \times f_{\text{ints_t}}$	—	—	kHz		
$f_{\text{loc_high}}$	Loss of external clock minimum frequency — RANGE = 01, 10, or 11	$(16/5) \times f_{\text{ints_t}}$	—	—	kHz		
FLL							
f_{dco}	DCO output frequency range	Low-range (DRS=00) $640 \times f_{\text{ints_t}}$	20	20.97	22	MHz	2, 3
		Mid-range (DRS=01) $1280 \times f_{\text{ints_t}}$	40	41.94	45	MHz	
		Mid-high range (DRS=10) $1920 \times f_{\text{ints_t}}$	60	62.91	67	MHz	
		High-range (DRS=11) $2560 \times f_{\text{ints_t}}$	80	83.89	90	MHz	
$f_{\text{dco_t_DMX32}}$	DCO output frequency	Low-range (DRS=00) $732 \times f_{\text{ints_t}}$	—	23.99	—	MHz	4, 5, 6

Table continues on the next page...

Table 17. MCG specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Mid-range (DRS=01) $1464 \times f_{\text{ints_t}}$	—	47.97	—	MHz	
	Mid-high range (DRS=10) $2197 \times f_{\text{ints_t}}$	—	71.99	—	MHz	
	High-range (DRS=11) $2929 \times f_{\text{ints_t}}$	—	95.98	—	MHz	
$J_{\text{cyc_fll}}$	FLL period jitter	—	70	140	ps	7
$t_{\text{fll_acquire}}$	FLL target frequency acquisition time	—	—	1	ms	8
PLL						
f_{vco}	VCO operating frequency	11.71875	12.288	14.6484375	MHz	
I_{pll}	PLL operating current <ul style="list-style-type: none"> IO 3.3 V current Max core voltage current 	—	300 100	—	μA	
$f_{\text{pll_ref}}$	PLL reference frequency range	31.25	32.768	39.0625	kHz	
$J_{\text{cyc_pll}}$	PLL period jitter (RMS) <ul style="list-style-type: none"> $f_{\text{vco}} = 12 \text{ MHz}$ 			700	ps	
D_{lock}	Lock entry frequency tolerance	± 1.49	—	± 2.98	%	
D_{unl}	Lock exit frequency tolerance	± 4.47	—	± 5.97	%	
$t_{\text{pll_lock}}$	Lock detector detection time	—	—	150×10^{-6} $+ 1075(1/f_{\text{pll_ref}})$	s	

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=0.
3. Chip maximum freq is 75 MHz, so high-range of DCO cannot be used and should not be configured.
4. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=1.
5. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
6. Chip max freq is 75 MHz, so High-range of DCO cannot be used and should not be configured.
7. This specification is based on standard deviation (RMS) of period or frequency.
8. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

3.2.2 Oscillator electrical specifications

3.2.2.1 Oscillator DC electrical specifications

Table 18. Oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V _{DD}	Supply voltage	1.71	—	3.6	V	
I _{DDOSC}	Supply current — low-power mode (HGO=0) <ul style="list-style-type: none"> 32 kHz 1 MHz 4 MHz 8 MHz (RANGE=01) 16 MHz 24 MHz 32 MHz 	—	500	—	nA	1
I _{DDOSC}	Supply current — high-gain mode (HGO=1) <ul style="list-style-type: none"> 32 kHz 1 MHz 4 MHz 8 MHz (RANGE=01) 16 MHz 24 MHz 32 MHz 	—	25	—	μA	1
C _x	EXTAL load capacitance	—	—	—		2, 3
C _y	XTAL load capacitance	—	—	—		2, 3
R _F	Feedback resistor — low-frequency, low-power mode (HGO=0)	—	—	—	MΩ	2, 4
	Feedback resistor — low-frequency, high-gain mode (HGO=1)	—	10	—	MΩ	
	Feedback resistor — high-frequency, low-power mode (HGO=0)	—	—	—	MΩ	
	Feedback resistor — high-frequency, high-gain mode (HGO=1)	—	1	—	MΩ	
R _S	Series resistor — low-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — low-frequency, high-gain mode (HGO=1)	—	200	—	kΩ	
	Series resistor — high-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — high-frequency, high-gain mode (HGO=1) <ul style="list-style-type: none"> 1 MHz resonator 2 MHz resonator 	—	6.6	—	kΩ	
		—	3.3	—	kΩ	

Table continues on the next page...

Table 18. Oscillator DC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	<ul style="list-style-type: none"> 4 MHz resonator 8 MHz resonator 16 MHz resonator 20 MHz resonator 32 MHz resonator 	—	0	—	k Ω	
V_{pp}^5	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	

- $V_{DD}=3.3$ V, Temperature =25 °C
- See crystal or resonator manufacturer's recommendation.
- C_x and C_y can be provided by using either integrated capacitors or external components.
- When low-power mode is selected, R_F is integrated and must not be attached externally.
- The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other device.

3.2.2.2 Oscillator frequency specifications

Table 19. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	
$f_{osc_hi_1}$	Oscillator crystal or resonator frequency — high-frequency mode (low range) (MCG_C2[RANGE]=01)	1	—	8	MHz	
$f_{osc_hi_2}$	Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x)	8	—	32	MHz	
f_{ec_extal}	Input clock frequency (external clock mode)	—	—	48	MHz	1, 2
t_{dc_extal}	Input clock duty cycle (external clock mode)	40	50	60	%	
t_{cst}	Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0)	—	—	—	ms	3, 4
	Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1)	—	—	—	ms	

Table continues on the next page...

Table 19. Oscillator frequency specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0)	—	0.6	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1)	—	1	—	ms	

1. Other frequency limits may apply when external clock is being used as a reference for the FLL or PLL.
2. When transitioning from FEI or FBI to FBE mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
3. Proper PC board layout procedures must be followed to achieve specifications.
4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

3.2.3 32 kHz oscillator electrical characteristics

3.2.3.1 32 kHz Oscillator Maximum Ratings

NOTE

Functional operating conditions are given in DC Electrical Specifications. Absolute Maximum Ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond those listed may affect device reliability or cause permanent damage to the device.

Table 20. 32 kHz oscillator absolute maximum ratings

Num	Symbol	Description	Min.	Max.	Unit
1	$V_{DD33OSC}$	RTC oscillator (A_IP_OSC_3v32k VLP_NN_C90LP) Module 3.3V Analog Supply Voltage	-0.3	3.6	V
2	V_{EXTAL}	EXTAL Input Voltage	-0.3	3.6	V
3	V_{XTAL}	XTAL Input Voltage	-0.3	3.6	V
4	T_A	Operating Temperature Range (Packaged)	-40	135	°C

Table continues on the next page...

Table 20. 32 kHz oscillator absolute maximum ratings (continued)

Num	Symbol	Description	Min.	Max.	Unit
5	T_J	Operating Temperature Range (Junction)	-40	135	°C
6	T_{stg}	Storage Temperature Range	-65	150	°C

3.2.3.2 32 kHz oscillator DC electrical specifications**Table 21. 32 kHz oscillator DC electrical specifications**

Symbol	Description	Min.	Typ.	Max.	Unit
V_{BAT}	Supply voltage	1.71	—	3.6	V
R_F	Internal feedback resistor	—	100	—	MΩ
C_{para}	Parasitical capacitance of EXTAL32 and XTAL32	—	5	7	pF
V_{pp}^1	Peak-to-peak amplitude of oscillation	—	0.6	—	V

1. When a crystal is being used with the 32 kHz oscillator, the EXTAL32 and XTAL32 pins should only be connected to required oscillator components and must not be connected to any other devices.

3.2.3.3 32 kHz oscillator frequency specifications**Table 22. 32 kHz Crystal and Oscillator Specifications**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Crystal frequency	—	32.768	—	kHz	
T_A	Operating temperature	-40	—	105	°C	1
	Total crystal frequency tolerance	-500	—	500	ppm	2,3
C_L	Load capacitance	—	12.5	—	pF	2
ESR	Equivalent series resistance	—	—	80	kOhms	2
t_{start}	Crystal start-up time	—	1000	—	ms	4
$f_{ec_extal32}$	External input clock frequency	—	32.768	—	kHz	5
V_{ec_xtal32}	External input clock amplitude	0.7	—	V_{DD}	V	6

1. Full temperature range of this device. A reduced range can be chosen to meet application needs.
2. Recommended crystal specification.
3. Sum of crystal initial frequency tolerance, crystal frequency stability, and aging tolerances given by crystal vendor.
4. Time from oscillator enable to clock stable. Dependent on the complete hardware configuration of the oscillator.
5. External oscillator connected to EXTAL32K. XTAL32K must be unconnected.
6. The parameter specified is a peak-to-peak value and V_{IH} and V_{IL} specifications do not apply. The voltage of the applied clock must be within the range of VSS to VDD.

3.3 Memories and memory interfaces

3.3.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

3.3.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 23. NVM program/erase timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{hvp4}	Longword Program high-voltage time	—	7.5	18	μ s	—
$t_{hversscr}$	Sector Erase high-voltage time	—	13	113	ms	1
$t_{hversall}$	Erase All high-voltage time	—			ms	1

1. Maximum time based on expectations at cycling end-of-life.

3.3.1.2 Flash timing specifications — commands

Table 24. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{pgmchk}	Program Check execution time	—	—	45	μ s	1
t_{rdsrc}	Read Resource execution time	—	—	30	μ s	1
t_{pgm4}	Program Longword execution time	—	65	145	μ s	—
t_{ersscr}	Erase Flash Sector execution time	—	14	114	ms	2
t_{rd1all}	Read 1s All Blocks execution time	—	—		ms	1
t_{rdonce}	Read Once execution time	—	—	25	μ s	1
$t_{pgmonce}$	Program Once execution time	—	65	—	μ s	—
t_{ersall}	Erase All Blocks execution time	—			ms	2
t_{vfykey}	Verify Backdoor Access Key execution time	—	—	30	μ s	1

Peripheral operating requirements and behaviors

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

3.3.1.3 Flash high voltage current behaviors

Table 25. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I _{DD_PGM}	Average current adder during high voltage flash programming operation	—	2.5	6.0	mA
I _{DD_ERS}	Average current adder during high voltage flash erase operation	—	1.5	4.0	mA

3.3.1.4 Reliability specifications

Table 26. NVM reliability specifications

Symbol	Description	Min.	Typ. ¹	Max.	Unit	Notes
Program Flash						
t _{nvmretp10k}	Data retention after up to 10 K cycles	5	50	—	years	—
t _{nvmretp1k}	Data retention after up to 1 K cycles	20	100	—	years	—
n _{nvmcycp}	Cycling endurance	10 K	50 K	—	cycles	2

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25 °C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at $-40\text{ °C} \leq T_j \leq 105\text{ °C}$.

3.4 Analog

3.4.1 ADC electrical specifications

All ADC channels meet the 12-bit single-ended accuracy specifications.

3.4.1.1 16-bit ADC operating conditions

Table 27. 16-bit ADC operating conditions

Symbol	Description	Conditions	Min.	Typ. ¹	Max.	Unit	Notes
V _{DDA}	Supply voltage	Absolute	1.71	—	3.6	V	
ΔV _{DDA}	Supply voltage	Delta to V _{DD} (V _{DD} – V _{DDA})	–100	0	+100	mV	2
ΔV _{SSA}	Ground voltage	Delta to V _{SS} (V _{SS} – V _{SSA})	–100	0	+100	mV	2

Table continues on the next page...

Table 27. 16-bit ADC operating conditions (continued)

Symbol	Description	Conditions	Min.	Typ. ¹	Max.	Unit	Notes
V _{REFH}	ADC reference voltage high	Absolute	V _{DDA}	V _{DDA}	V _{DDA}	V	3
V _{REFL}	ADC reference voltage low	Absolute	V _{SSA}	V _{SSA}	V _{SSA}	V	4
V _{ADIN}	Input voltage		V _{SSA}	—	V _{DDA}	V	
C _{ADIN}	Input capacitance	<ul style="list-style-type: none"> 16-bit mode 8-bit / 10-bit / 12-bit modes 	—	8	10	pF	
R _{ADIN}	Input series resistance		—	2	5	kΩ	
R _{AS}	Analog source resistance (external)	12-bit modes f _{ADCK} < 4 MHz	—	—	5	kΩ	5
f _{ADCK}	ADC conversion clock frequency	≤ 12-bit mode	1.0	—	18.0	MHz	6
f _{ADCK}	ADC conversion clock frequency	16-bit mode	2.0	—	12.0	MHz	6
C _{rate}	ADC conversion rate	≤ 12-bit modes No ADC hardware averaging Continuous conversions enabled, subsequent conversion time	20.000	—	818.330	kS/s	7
C _{rate}	ADC conversion rate	16-bit mode No ADC hardware averaging Continuous conversions enabled, subsequent conversion time	37.037	—	461.467	kS/s	7

1. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 1.0 MHz, unless otherwise stated. Typical values are for reference only, and are not tested in production.
2. DC potential difference.
3. V_{REFH} is internally tied to V_{DDA}.
4. V_{REFL} is internally tied to V_{SSA}.
5. This resistance is external to MCU. To achieve the best results, the analog source resistance must be kept as low as possible. The results in this data sheet were derived from a system that had < 8 Ω analog source resistance. The R_{AS}/C_{AS} time constant should be kept to < 1 ns.
6. To use the maximum ADC conversion clock frequency, CFG2[ADHSC] must be set and CFG1[ADLPC] must be clear.
7. For guidelines and examples of conversion rate calculation, download the [ADC calculator tool](#).

Peripheral operating requirements and behaviors

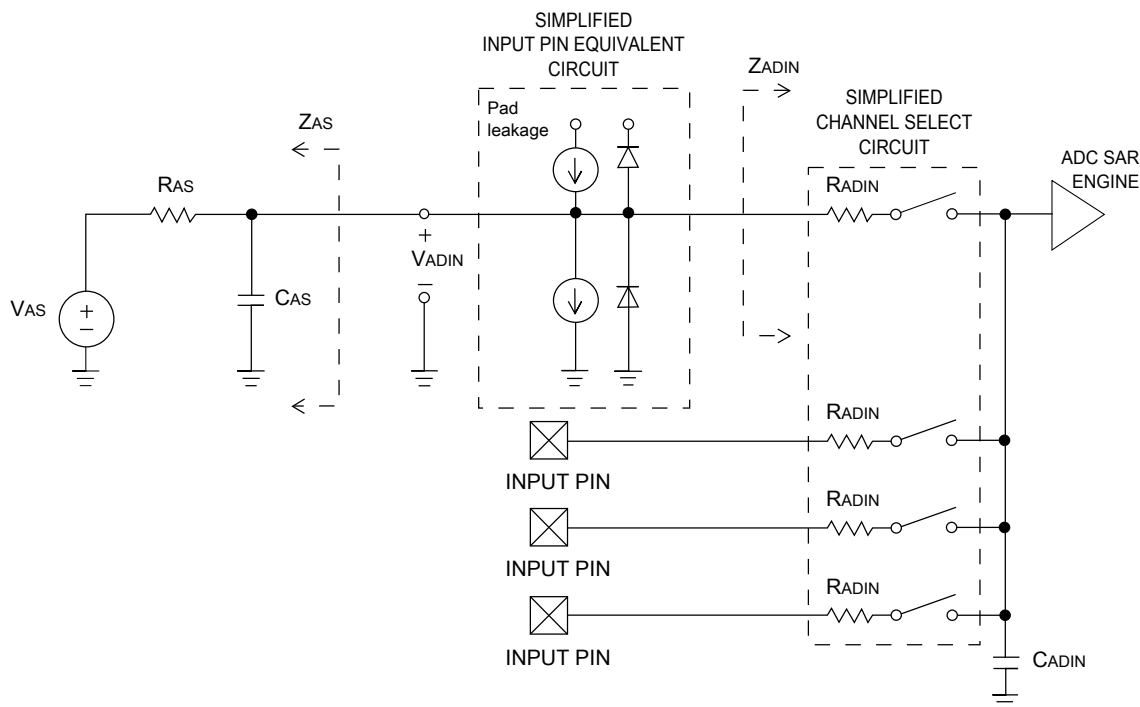


Figure 3. ADC input impedance equivalency diagram

3.4.1.2 16-bit ADC electrical characteristics

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$)

Symbol	Description	Conditions ¹	Min.	Typ. ²	Max.	Unit	Notes
I_{DDA_ADC}	Supply current		0.215	—	1.7	mA	3
f_{ADACK}	ADC asynchronous clock source	• ADLPC = 1, ADHSC = 0	1.2	2.4	3.9	MHz	$t_{ADACK} = 1/f_{ADACK}$
		• ADLPC = 1, ADHSC = 1	2.4	4.0	6.1	MHz	
		• ADLPC = 0, ADHSC = 0	3.0	5.2	7.3	MHz	
		• ADLPC = 0, ADHSC = 1	4.4	6.2	9.5	MHz	
	Sample Time	See Reference Manual chapter for sample times					
TUE	Total unadjusted error	• 12-bit modes • <12-bit modes	—	±4 ±1.4	±6.8 ±2.1	LSB ⁴	5
DNL	Differential non-linearity	• 12-bit modes	—	±0.7	-1.1 to +1.9	LSB ⁴	5
		• <12-bit modes	—	±0.2	-0.3 to +0.5		
INL	Integral non-linearity	• 12-bit modes	—	±1.0	-2.7 to +1.9	LSB ⁴	5
			—	±0.5			

Table continues on the next page...

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

Symbol	Description	Conditions ¹	Min.	Typ. ²	Max.	Unit	Notes
		<ul style="list-style-type: none"> <12-bit modes 			-0.7 to +0.5		
E_{FS}	Full-scale error	<ul style="list-style-type: none"> 12-bit modes <12-bit modes 	—	-4	-5.4	LSB ⁴	$V_{ADIN} = V_{DDA}$ ⁵
E_Q	Quantization error	<ul style="list-style-type: none"> 16-bit modes 12-bit modes 	—	-1 to 0	—	LSB ⁴	
ENOB	Effective number of bits	16-bit single-ended mode					6
		<ul style="list-style-type: none"> Avg = 32 	12.8	14.5		bits	
		<ul style="list-style-type: none"> Avg = 4 	11.9	13.8	—	bits	
					—	bits	
					12.2	13.9	—
			11.4	13.1	—		
SINAD	Signal-to-noise plus distortion	See ENOB	6.02 × ENOB + 1.76			dB	
THD	Total harmonic distortion	16-bit single-ended mode				dB	7
		<ul style="list-style-type: none"> Avg = 32 	—	-94	—	dB	
			—	-85	—		
SFDR	Spurious free dynamic range	16-bit single-ended mode				dB	7
		<ul style="list-style-type: none"> Avg = 32 	82	95	—	dB	
			78	90	—		
E_{IL}	Input leakage error		$I_{in} \times R_{AS}$			mV	I_{in} = leakage current (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	Across the full temperature range of the device	1.55	1.62	1.69	mV/°C	8
V_{TEMP25}	Temp sensor voltage	25 °C	706	716	726	mV	8

1. All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{DDA}$

2. Typical values assume $V_{DDA} = 3.0$ V, Temp = 25 °C, $f_{ADCK} = 2.0$ MHz unless otherwise stated. Typical values are for reference only and are not tested in production.

Peripheral operating requirements and behaviors

3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. $1 \text{ LSB} = (V_{\text{REFH}} - V_{\text{REFL}})/2^N$
5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
6. Input data is 100 Hz sine wave. ADC conversion clock < 12 MHz.
7. Input data is 1 kHz sine wave. ADC conversion clock < 12 MHz.
8. ADC conversion clock < 3 MHz

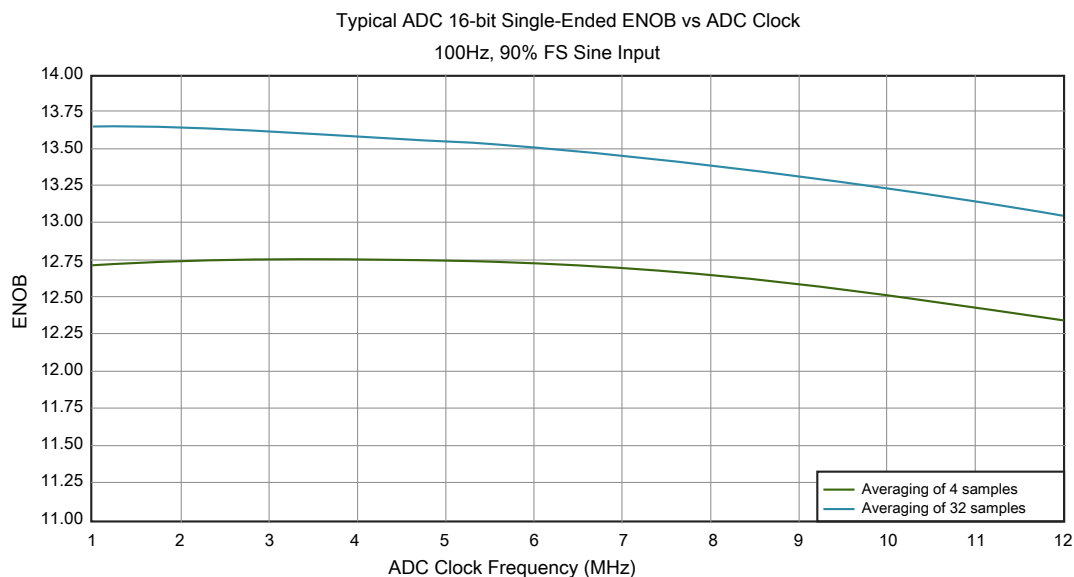


Figure 4. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

3.4.2 CMP and 6-bit DAC electrical specifications

Table 29. Comparator and 6-bit DAC electrical specifications

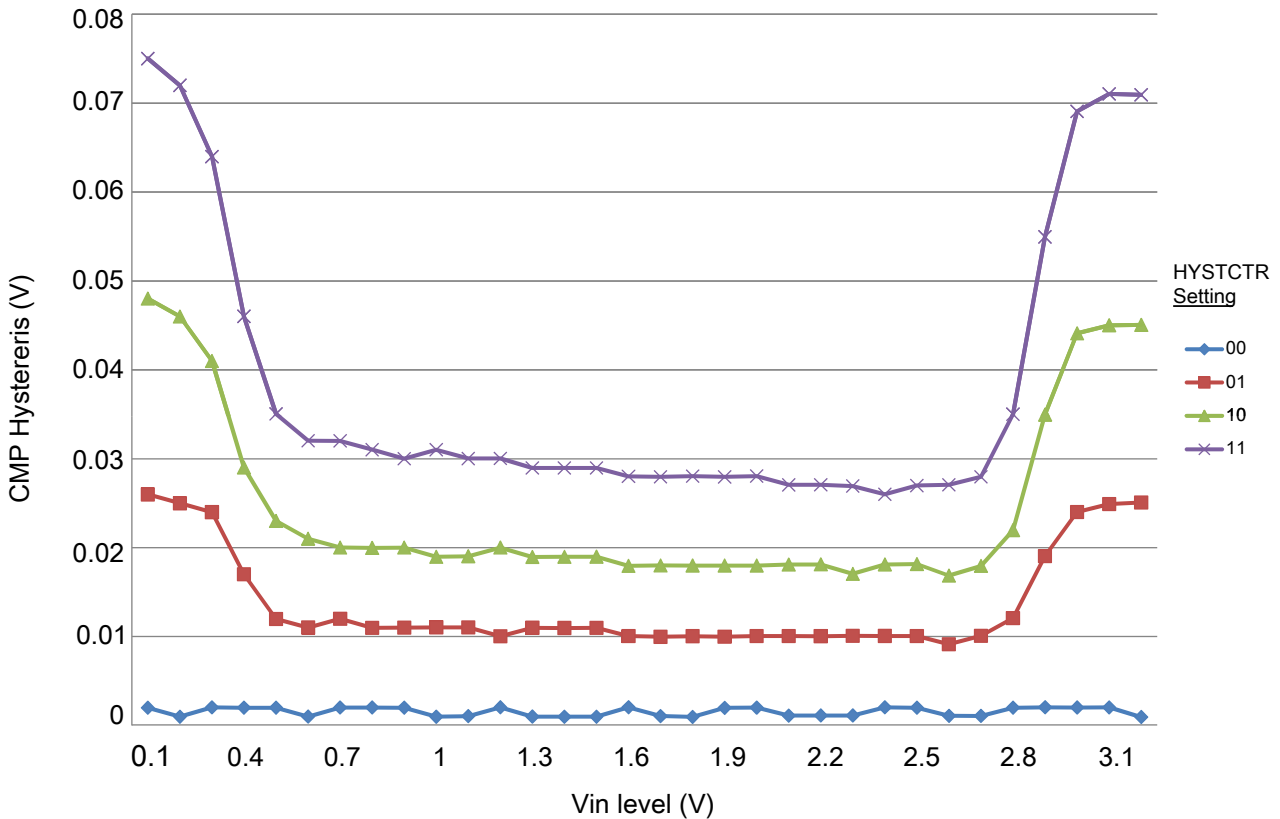
Symbol	Description	Min.	Typ.	Max.	Unit
V_{DD}	Supply voltage	1.71	—	3.6	V
I_{DDHS}	Supply current, high-speed mode (EN=1, PMODE=1)	—	—	200	μA
$I_{\text{DDL S}}$	Supply current, low-speed mode (EN=1, PMODE=0)	—	—	20	μA
V_{AIN}	Analog input voltage	$V_{\text{SS}} - 0.3$	—	V_{DD}	V
V_{AIO}	Analog input offset voltage	—	—	20	mV
V_{H}	Analog comparator hysteresis ¹ <ul style="list-style-type: none"> • CR0[HYSTCTR] = 00 • CR0[HYSTCTR] = 01 • CR0[HYSTCTR] = 10 • CR0[HYSTCTR] = 11 	—	5 10 20 30	—	mV
V_{CMPOh}	Output high	$V_{\text{DD}} - 0.5$	—	—	V

Table continues on the next page...

Table 29. Comparator and 6-bit DAC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit
V_{CMPOI}	Output low	—	—	0.5	V
t_{DHS}	Propagation delay, high-speed mode (EN=1, PMODE=1)	20	50	200	ns
t_{DLS}	Propagation delay, low-speed mode (EN=1, PMODE=0)	80	250	600	ns
	Analog comparator initialization delay ²	—	—	40	μ s
I_{DAC6b}	6-bit DAC current adder (enabled)	—	7	—	μ A
INL	6-bit DAC integral non-linearity	-0.5	—	0.5	LSB ³
DNL	6-bit DAC differential non-linearity	-0.3	—	0.3	LSB

1. Typical hysteresis is measured with input voltage range limited to 0.6 to $V_{DD}-0.6$ V.
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to CMP_DACCR[DACEN], CMP_DACCR[VRSEL], CMP_DACCR[VOSEL], CMP_MUXCR[PSEL], and CMP_MUXCR[MSEL]) and the comparator output settling to a stable level.
3. 1 LSB = $V_{reference}/64$

**Figure 5. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 0)**

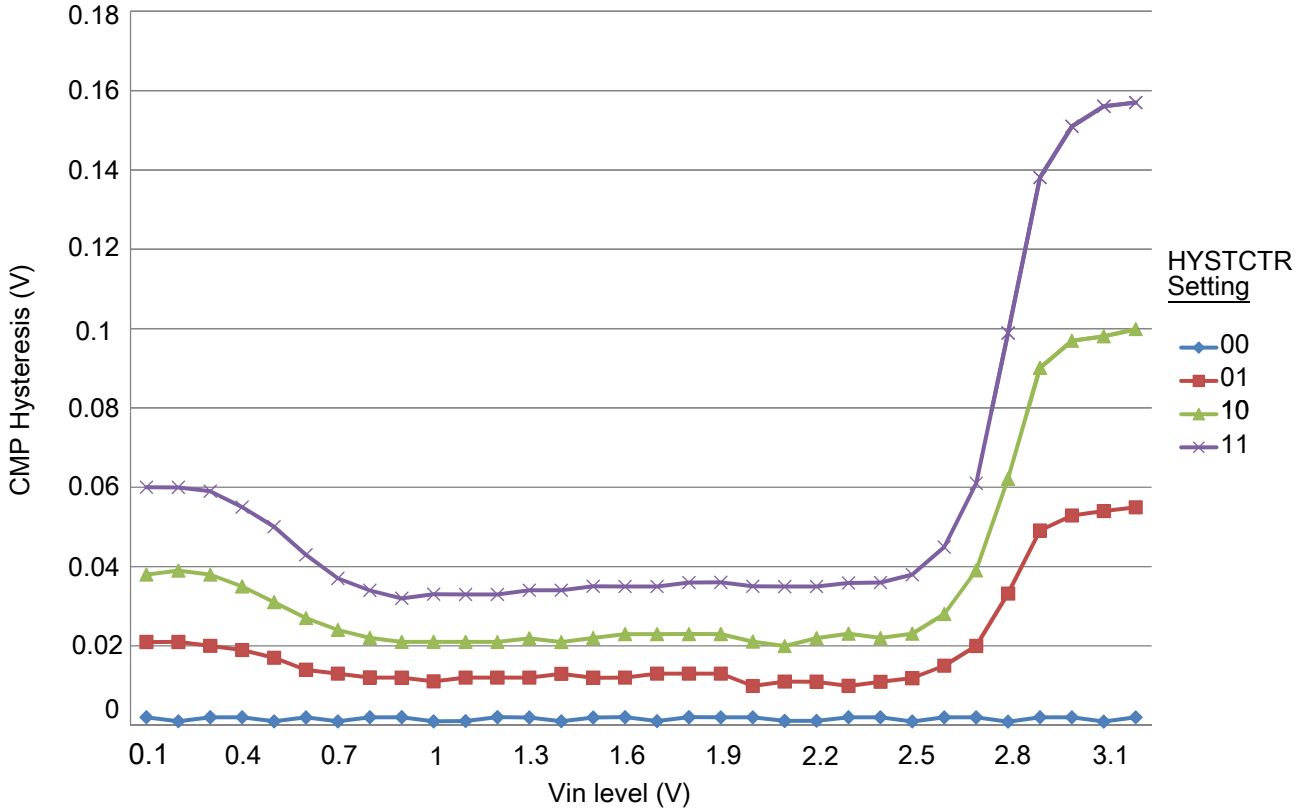


Figure 6. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 1)

3.4.3 Voltage reference electrical specifications

Table 30. 1.2 VREF full-range operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DDA}	Supply voltage	2.7 ¹	3.6	V	
T_A	Temperature	-40	105	°C	
C_L	Output load capacitance	100		nF	2, 3

1. AFE is enabled.
2. C_L must be connected between VREFH and VREFL.
3. The load capacitance should not exceed $\pm 25\%$ of the nominal specified C_L value over the operating temperature range of the device.

Table 31. VREF full-range operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
VREFH	Voltage reference output with factory trim at nominal V_{DDA} and temperature = 25 °C	1.1915	1.195	1.2027	V	
VREFH	Voltage reference output with — factory trim	1.1584	—	1.2376	V	
VREFH	Voltage reference output — user trim	1.178	—	1.202	V	
VREFL	Voltage reference output	0.38	0.4	0.42	V	
V_{step}	Voltage reference trim step	—	0.5	—	mV	
V_{tdrift}	Temperature drift when ICOMP = 0 across full temperature range	—	18	—	ppm/°C	
	Temperature drift when ICOMP = 1 across full temperature range	—	6	—	ppm/°C	1
	Temperature drift when ICOMP = 1 across -40 °C to 70 °C	—	5	—	ppm/°C	1, 2
	Temperature drift when ICOMP = 1 across 0 °C to 50 °C	—	3	—	ppm/°C	1, 2
Ac	Aging coefficient	—	—	400	uV/yr	
I_{bg}	Bandgap only current	—	—	80	μA	2
I_{lp}	Low-power buffer current	—	—	0.19	mA	2
I_{hp}	High-power buffer current	—	—	0.5	mA	2
I_{LOAD}	VREF buffer current	-2	—	2	mA	3, 4
ΔV_{LOAD}	Load regulation • current = ± 1.0 mA	—	200	—	μV	2, 5
T_{stup}	Buffer startup time	—	—	200	μs	
$T_{chop_osc_stup}$	Internal bandgap start-up delay with chop oscillator enabled	—	—	20	ms	
V_{vdrift}	Voltage drift (VREFHmax -VREFHmin across the full voltage range)	—	0.5	—	mV	2

1. ICOMP=1 is recommended to get best temperature drift. CHOPEN bit = 1 is also recommended.
2. See the chip's Reference Manual for the appropriate settings of VREF Status and Control register.
3. 2 mA I_{LOAD} is only achievable for above 2.7 V V_{DDA} condition.
4. See the chip's Reference Manual for the appropriate settings of SIM Miscellaneous Control register.
5. Load regulation voltage is the difference between VREFH voltage with no load vs. voltage with defined load.

NOTE

Temperature drift per degree is ((VREFHmax-VREFHmin)/ (temperature range)/VREFHmin) in ppm/°C.

3.4.4 AFE electrical specifications

3.4.4.1 $\Sigma\Delta$ ADC + PGA specifications

Table 32. $\Sigma\Delta$ ADC + PGA specifications

Symbol	Description	Conditions	Min	Typ ¹	Max	Unit	Notes			
f_{Nyq}	Input bandwidth	Normal Mode	1.5	1.5	1.5	kHz				
		Low-Power Mode	1.5	1.5	1.5					
V_{CM}	Input Common Mode Reference		0		0.8	V				
$V_{IN_{diff}}$	Differential input range	Gain = 1 (PGA ON/OFF) ²		± 500		mV				
		Gain = 2		± 250		mV				
		Gain = 4		± 125		mV				
		Gain = 8		± 62		mV				
		Gain = 16		± 31		mV				
		Gain = 32		± 15		mV				
SNR	Signal to Noise Ratio	Normal Mode				dB				
		• $f_{IN}=50$ Hz; gain=01, common mode=0 V, $V_{pp}=1000$ mV (full range diff.)	90	92						
		• $f_{IN}=50$ Hz; gain=02, common mode=0 V, $V_{pp}= 500$ mV (differential ended)	88	90						
		• $f_{IN}=50$ Hz; gain=04, common mode=0 V, $V_{pp}= 250$ mV (differential ended)	82	86						
		• $f_{IN}=50$ Hz; gain=08, common mode=0 V, $V_{pp}= 125$ mV (differential ended)	76	82						
		• $f_{IN}=50$ Hz; gain=16, common mode=0 V, $V_{pp}= 62$ mV (differential ended)	70	78						
		• $f_{IN}=50$ Hz; gain=32, common mode=0 V, $V_{pp}= 31$ mV (differential ended)	64	74						
		Low-Power Mode							dB	
		• $f_{IN}=50$ Hz; gain=01, common mode=0 V, $V_{pp}=1000$ mV (full range diff.)	82	82						
		• $f_{IN}=50$ Hz; gain=02, common mode=0 V, $V_{pp}= 500$ mV (differential ended)	76	78						
• $f_{IN}=50$ Hz; gain=04, common mode=0 V, $V_{pp}= 250$ mV (differential ended)	70	74								
• $f_{IN}=50$ Hz; gain=08, common mode=0 V, $V_{pp}= 125$ mV (differential ended)	64	70								

Table continues on the next page...

Table 32. $\Sigma\Delta$ ADC + PGA specifications (continued)

Symbol	Description	Conditions	Min	Typ ¹	Max	Unit	Notes
		<ul style="list-style-type: none"> $f_{IN}=50$ Hz; gain=16, common mode=0 V, $V_{pp}=62$ mV (differential ended) $f_{IN}=50$ Hz; gain=32, common mode=0 V, $V_{pp}=31$ mV (differential ended) 	58	66			
			52	62			
SINAD	Signal-to-Noise + Distortion Ratio	Normal Mode <ul style="list-style-type: none"> $f_{IN}=50$ Hz; gain=01, common mode=0 V, $V_{pp}=500$ mV (differential ended) 		78		dB	
		Low-Power Mode <ul style="list-style-type: none"> $f_{IN}=50$ Hz; gain=01, common mode=0 V, $V_{pp}=500$ mV (differential ended) 		74		dB	
CMMR	Common Mode Rejection Ratio	<ul style="list-style-type: none"> $f_{IN}=50$ Hz; gain=01, common mode=0 V, $V_{id}=100$ mV $f_{IN}=50$ Hz; gain=32, common mode=0 V, $V_{id}=100$ mV 		70		dB	
E_{offset}	Offset Error	Gain=01, $V_{pp}=1000$ mV (full range diff.)			± 5	mV	
$\Delta Offset_{Temp}$	Offset Temperature Drift ³	Gain=01, $V_{pp}=1000$ mV (full range diff.)			± 25	ppm/ $^{\circ}$ C	
$\Delta Gain_{Temp}$	Gain Temperature Drift - Gain error caused by temperature drifts ⁴	<ul style="list-style-type: none"> Gain=01, $V_{pp}=500$ mV (differential ended) Gain=32, $V_{pp}=15$ mV (differential ended) 			± 75	ppm/ $^{\circ}$ C	
PSRR _{AC}	AC Power Supply Rejection Ratio	Gain=01, $V_{CC} = 3\text{ V} \pm 100$ mV, $f_{IN} = 50$ Hz		60		dB	
XT	Crosstalk (with the input of the affected channel grounded)	Gain=01, $V_{id} = 500$ mV, $f_{IN} = 50$ Hz			-100	dB	
f_{MCLK}	Modulator Clock Frequency Range	Normal Mode	0.03		6.5	MHz	
		Low-Power Mode	0.03		1.6		
I_{DDA_PGA}	Current consumption by PGA (each channel)	Normal Mode ($f_{MCLK} = 6.144$ MHz, OSR= 2048)			2.6	mA	5
		Low-Power Mode ($f_{MCLK} = 0.768$ MHz, OSR= 256)			0		
I_{DDA_ADC}	Current Consumption by ADC (each channel)	Normal Mode ($f_{MCLK} = 6.144$ MHz, OSR= 2048)			1.4	mA	
		Low-Power Mode ($f_{MCLK} = 0.768$ MHz, OSR= 256)			0.5		

1. Typical values assume $V_{DDA} = 3.0$ V, Temp = 25 $^{\circ}$ C, $f_{MCLK} = 6.144$ MHz, OSR = 2048 for Normal mode and $f_{MCLK} = 768$ kHz, OSR = 256 for low-power mode unless otherwise stated. All values are for reference only and are not tested in production.
2. The full-scale input range in single-ended mode is $0.5 V_{pp}$.
3. Represents combined offset temperature drift of the PGA, SD ADC, and Internal 1.2 VREF blocks; Defined by shorting both differential inputs to ground.

Peripheral operating requirements and behaviors

4. Represents combined gain temperature drift of the PGA, SD ADC and Internal 1.2 VREF blocks.
5. PGA is disabled in low-power modes.

3.4.4.2 $\Sigma\Delta$ ADC Standalone specifications

Table 33. $\Sigma\Delta$ ADC standalone specifications

Symbol	Description	Conditions	Min	Typ ¹	Max	Unit	Notes
f_{Nyq}	Input bandwidth	Normal Mode	1.5	1.5	1.5	kHz	
		Low-Power Mode	1.5	1.5	1.5		
V_{CM}	Input Common Mode Reference		0		0.8	V	
V_{INdiff}	Input range	Differential		± 500		mV	
		Single-Ended		± 250		mV	
SNR	Signal to Noise Ratio	Normal Mode				dB	
		<ul style="list-style-type: none"> • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (differential ended) • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (full range se.) 	88	90			
		Low-Power Mode					
		<ul style="list-style-type: none"> • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (diff.) • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (full range se.) 	76	78			
$\Delta Gain_{Temp}$	Gain Temperate Drift - Gain error caused by temperature drifts ²	<ul style="list-style-type: none"> • Gain bypassed $V_{pp} = 500$ mV (differential) • PGA bypassed $V_{pp} = 500$ mV (differential), $V_{CM} = 0$ V 			55	ppm/°C	
$\Delta Offset_{Temp}$	Offset Temperate Drift - Offset error caused by temperature drifts ³	<ul style="list-style-type: none"> • Gain bypassed $V_{pp} = 500$ mV (differential), $V_{CM} = 0$ V 			30	ppm/°C	
SINAD	Signal-to-Noise + Distortion Ratio	Normal Mode				dB	
		<ul style="list-style-type: none"> • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (diff.) • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (full range se.) 		80			
		Low-Power Mode					
		<ul style="list-style-type: none"> • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (diff.) • $f_{IN}=50$ Hz; common mode=0 V, $V_{pp}=500$ mV (full range se.) 		74			
CMMR	Common Mode Rejection Ratio	<ul style="list-style-type: none"> • $f_{IN}=50$ Hz; common mode=0 V, $V_{id}=100$ mV 		90		dB	

Table continues on the next page...

Table 33. $\Sigma\Delta$ ADC standalone specifications (continued)

Symbol	Description	Conditions	Min	Typ ¹	Max	Unit	Notes
PSRR _{AC}	AC Power Supply Rejection Ratio	Gain=01, V _{CC} = 3 V ± 100 mV, f _{IN} = 50 Hz		60		dB	
XT	Crosstalk	Gain=01, V _{id} = 500 mV, f _{IN} = 50 Hz			-100	dB	
f _{MCLK}	Modulator Clock Frequency Range	Normal Mode Low-Power Mode	0.03 0.03		6.5 1.6	MHz	
I _{DDA_ADC}	Current Consumption by ADC (each channel)	Normal Mode (f _{MCLK} = 6.144 MHz, OSR= 2048) Low-Power Mode (f _{MCLK} = 0.768 MHz, OSR= 256)			1.4 0.5	mA	

1. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{MCLK} = 6.144 MHz, OSR = 2048 for Normal mode and f_{MCLK} = 768 kHz, OSR = 256 for low-power mode unless otherwise stated. Typical values are for reference only and are not tested in production.
2. Represents combined gain temperature drift of the SD ADC, and Internal 1.2 VREF blocks.
3. Represents combined offset temperature drift of the SD ADC, and Internal 1.2 VREF blocks; Defined by shorting both differential inputs to ground.

3.4.4.3 External modulator interface

The external modulator interface on this device comprises of a Clock signal and 1-bit data signal. Depending on the modulator device being used, the interface works as follows:

- Clock supplied to external modulator which drives data on rising edge and the KM35 device captures it on falling edge or next rising edge.
- Clock and data are supplied by external modulator and KM35 device can sample it on falling edge or next rising edge.

Depending on control bit in AFE, the sampling edge is changed.

3.5 Timers

See [General switching specifications](#).

3.6 Communication interfaces

3.6.1 I2C switching specifications

See [General switching specifications](#).

3.6.2 UART switching specifications

See [General switching specifications](#).

3.6.3 SPI switching specifications

The Serial Peripheral Interface (SPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The following tables provide timing characteristics for classic SPI timing modes. See the SPI chapter of the chip's Reference Manual for information about the modified transfer formats used for communicating with slower peripheral devices.

All timing is shown with respect to 20% V_{DD} and 80% V_{DD} thresholds, unless noted, as well as input signal transitions of 3 ns and a 30 pF maximum load on all SPI pins.

Table 34. SPI master mode timing on slew rate disabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	$f_{periph}/2048$	$f_{periph}/2$	Hz	1
2	t_{SPSCK}	SPSCK period	$2 \times t_{periph}$	$2048 \times t_{periph}$	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	$t_{periph} - 30$	$1024 \times t_{periph}$	ns	—
6	t_{SU}	Data setup time (inputs)	18	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	15	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	$t_{periph} - 25$	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For both SPI0 and SPI1, f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$

Table 35. SPI master mode timing on slew rate enabled pads

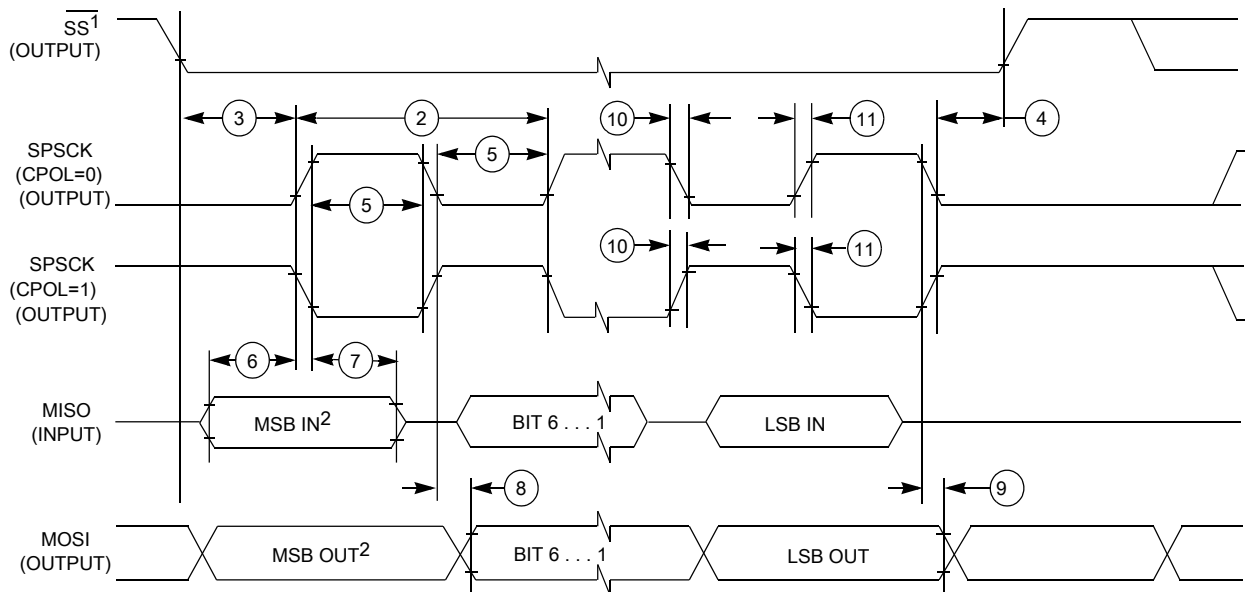
Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	$f_{periph}/2048$	$f_{periph}/2$	Hz	1

Table continues on the next page...

Table 35. SPI master mode timing on slew rate enabled pads (continued)

Num.	Symbol	Description	Min.	Max.	Unit	Note
2	t_{SPSCK}	SPSCK period	$2 \times t_{periph}$	$2048 \times t_{periph}$	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	$t_{periph} - 30$	$1024 \times t_{periph}$	ns	—
6	t_{SU}	Data setup time (inputs)	96	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	52	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	$t_{periph} - 25$	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

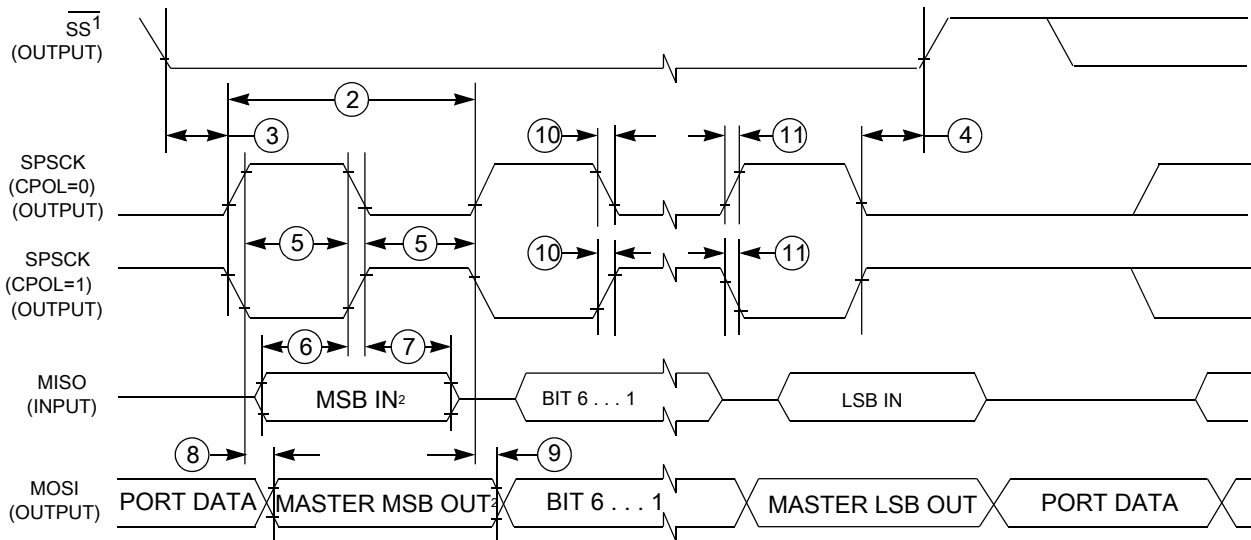
- For both SPI0 and SPI1, f_{periph} is the system clock (f_{sys}).
- $t_{periph} = 1/f_{periph}$



- If configured as an output.
- LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 7. SPI master mode timing (CPHA = 0)

Peripheral operating requirements and behaviors



1. If configured as output
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure 8. SPI master mode timing (CPHA = 1)

Table 36. SPI slave mode timing on slew rate disabled pads

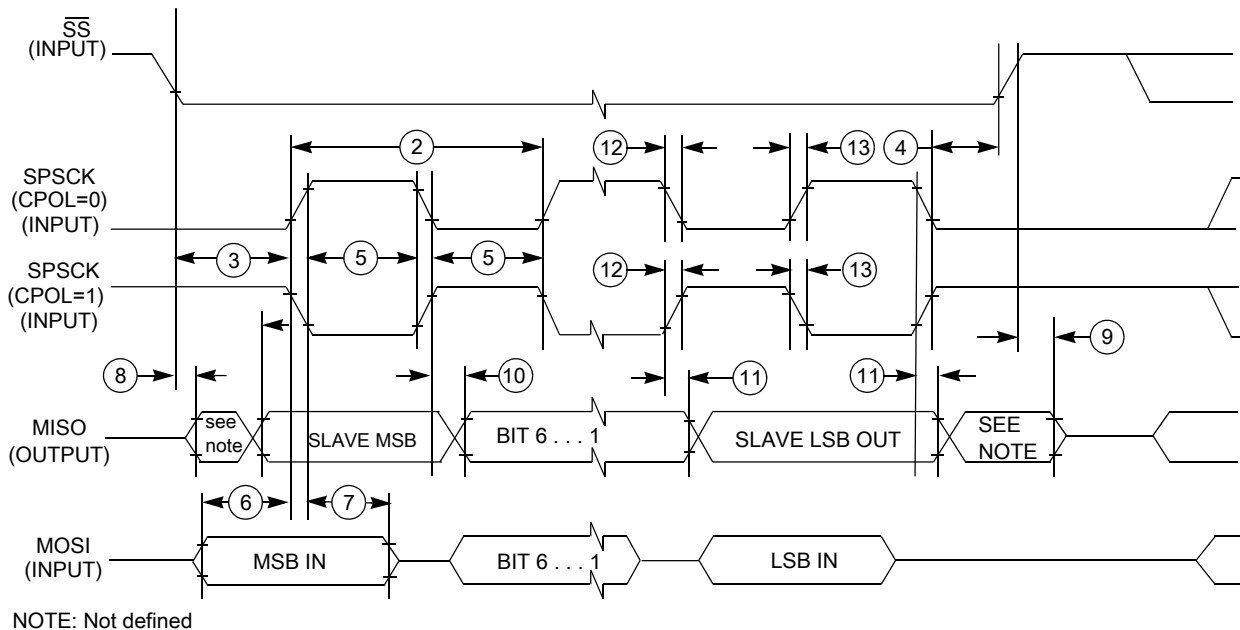
Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	t_{SPSCCK}	SPSCCK period	$4 \times t_{periph}$	—	ns	2
3	t_{Lead}	Enable lead time	1	—	t_{periph}	—
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	$t_{WSPSCCK}$	Clock (SPSCCK) high or low time	$t_{periph} - 30$	—	ns	—
6	t_{SU}	Data setup time (inputs)	2.5	—	ns	—
7	t_{HI}	Data hold time (inputs)	3.5	—	ns	—
8	t_a	Slave access time	—	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	—	t_{periph}	ns	4
10	t_v	Data valid (after SPSCCK edge)	—	31	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	$t_{periph} - 25$	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For both SPI0 and SPI1, f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

Table 37. SPI slave mode timing on slew rate enabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	t_{SPSCK}	SPSCK period	$4 \times t_{periph}$	—	ns	2
3	t_{Lead}	Enable lead time	1	—	t_{periph}	—
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	$t_{periph} - 30$	—	ns	—
6	t_{SU}	Data setup time (inputs)	2	—	ns	—
7	t_{HI}	Data hold time (inputs)	7	—	ns	—
8	t_a	Slave access time	—	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	—	t_{periph}	ns	4
10	t_v	Data valid (after SPSCK edge)	—	122	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	$t_{periph} - 25$	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

1. For both SPI0 and SPI1, f_{periph} is the system clock (f_{sys}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

**Figure 9. SPI slave mode timing (CPHA = 0)**

Peripheral operating requirements and behaviors

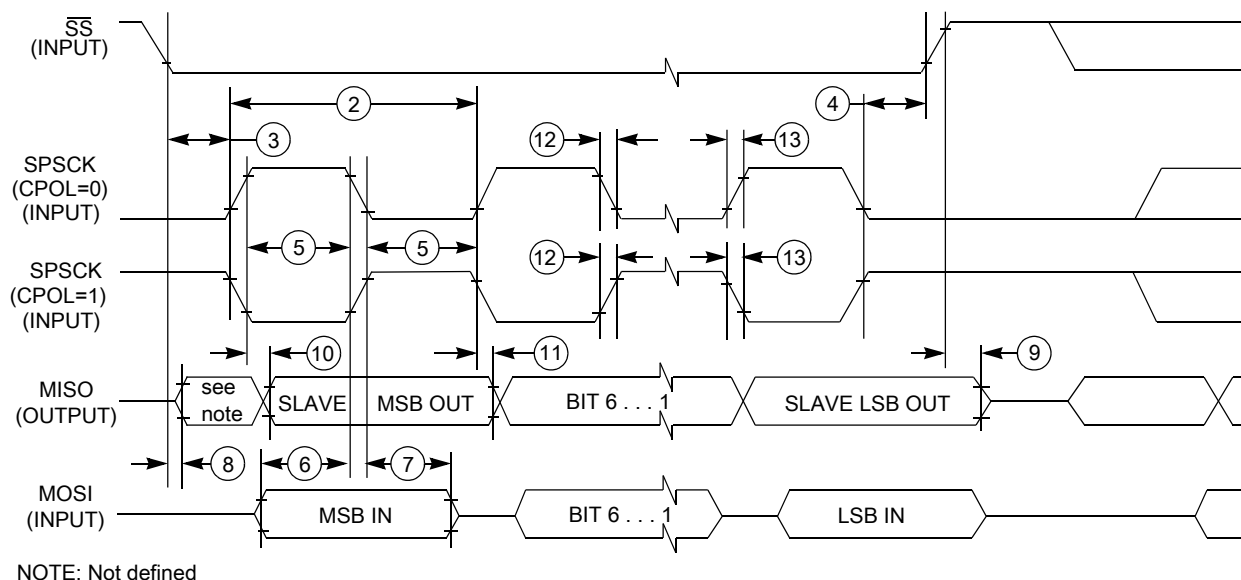


Figure 10. SPI slave mode timing (CPHA = 1)

3.7 Human-Machine Interfaces (HMI)

3.7.1 LCD electrical characteristics

Table 38. LCD electricals

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{Frame}	LCD frame frequency					
	<ul style="list-style-type: none"> GCR[FFR]=0 GCR[FFR]=1 	23.3	—	73.1	Hz	
C_{LCD}	LCD charge pump capacitance — nominal value	—	100	—	nF	
C_{BYLCD}	LCD bypass capacitance — nominal value	—	100	—	nF	1
C_{Glass}	LCD glass capacitance	—	2000	8000	pF	2
V_{IREG}	V_{IREG}				V	3
	<ul style="list-style-type: none"> RVTRIM=0000 	—	0.91	—		
	<ul style="list-style-type: none"> RVTRIM=1000 	—	0.92	—		
	<ul style="list-style-type: none"> RVTRIM=0100 	—	0.93	—		
	<ul style="list-style-type: none"> RVTRIM=1100 	—	0.94	—		
	<ul style="list-style-type: none"> RVTRIM=0010 	—	0.96	—		
	<ul style="list-style-type: none"> RVTRIM=1010 	—	0.97	—		
	<ul style="list-style-type: none"> RVTRIM=0110 	—	0.98	—		

Table continues on the next page...

Table 38. LCD electricals (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	<ul style="list-style-type: none"> RVTRIM=1110 RVTRIM=0001 RVTRIM=1001 RVTRIM=0101 RVTRIM=1101 RVTRIM=0011 RVTRIM=1011 RVTRIM=0111 RVTRIM=1111 	—	1.01	—		
Δ_{RTRIM}	V_{IREG} TRIM resolution	—	—	3.0	% V_{IREG}	
I_{VIREG}	V_{IREG} current adder — RVEN = 1	—	1	—	μA	
I_{RBIAS}	RBIAS current adder <ul style="list-style-type: none"> LADJ = 10 or 11 — High load (LCD glass capacitance ≤ 8000 pF) LADJ = 00 or 01 — Low load (LCD glass capacitance ≤ 2000 pF) 	—	10	—	μA	
R_{RBIAS}	RBIAS resistor values <ul style="list-style-type: none"> LADJ = 10 or 11 — High load (LCD glass capacitance ≤ 8000 pF) LADJ = 00 or 01 — Low load (LCD glass capacitance ≤ 2000 pF) 	—	0.28	—	$M\Omega$	
VLL1	VLL1 voltage	—	—	V_{IREG}	V	4
VLL2	VLL2 voltage	—	—	$2 \times V_{IREG}$	V	4
VLL3	VLL3 voltage	—	—	$3 \times V_{IREG}$	V	4
VLL1	VLL1 voltage	—	—	$V_{DDA} / 3$	V	5
VLL2	VLL2 voltage	—	—	$V_{DDA} / 1.5$	V	5
VLL3	VLL3 voltage	—	—	V_{DDA}	V	5

- The actual value used could vary with tolerance.
- For highest glass capacitance values, LCD_GCR[LADJ] should be configured as specified in the LCD Controller chapter within the device's reference manual.
- V_{IREG} maximum should never be externally driven to any level other than $V_{DD} - 0.15$ V
- VLL1, VLL2 and VLL3 are a function of V_{IREG} only when the regulator is enabled (GCR[RVEN]=1) and the charge pump is enabled (GCR[CPSEL]=1).
- VLL1, VLL2 and VLL3 are a function of V_{DDA} only under either of the following conditions:
 - The charge pump is enabled (GCR[CPSEL]=1), the regulator is disabled (GCR[RVEN]=0), and VLL3 = V_{DDA} through the internal power switch (GCR[VSUPPLY]=0).
 - The resistor bias string is enabled (GCR[CPSEL]=0), the regulator is disabled (GCR[RVEN]=0), and VLL3 is connected to V_{DDA} externally (GCR[VSUPPLY]=1).

4 Dimensions

4.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to nxp.com and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
100-pin LQFP	98ASS23308W
144-pin LQFP	98ASS23177W

5 Pinout

5.1 KM35 Signal multiplexing and pin assignments

NOTE

If use SLCD Fault Detection function, then corresponding SLCD functions at ALT6 or ALT7 need to be enabled. Otherwise don't need to enable them.

Table 39. Signal Multiplexing and Pin Assignments

100 LQFP	144 LQFP	Pin Name	DEFAU LT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
—	143	PTI4	LCD_P4 4	LCD_P4 4	PTI4	—	—	—	—	—	LCD_P4 4
—	144	NC	NC	NC	—	—	—	—	—	—	—
—	1	NC	NC	NC	—	—	—	—	—	—	—
—	2	NC	NC	NC	—	—	—	—	—	—	—
—	3	PTI5	LCD_P4 5	LCD_P4 5	PTI5	—	—	—	—	—	LCD_P4 5
1	4	PTA0/ LLWU_P 16	LCD_P2 3	LCD_P2 3	PTA0/ LLWU_P 16	—	—	—	—	—	LCD_P2 3

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAU LT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
2	5	PTA1	LCD_P2 4	LCD_P2 4	PTA1	—	—	—	—	—	LCD_P2 4
—	6	PTI6	LCD_P4 6	LCD_P4 6	PTI6	UART2_ RX	—	—	—	—	LCD_P4 6
—	7	PTI7	LCD_P4 7	LCD_P4 7	PTI7	UART2_ TX	—	—	—	—	LCD_P4 7
3	8	PTA2	LCD_P2 5	LCD_P2 5	PTA2	—	—	—	—	—	LCD_P2 5
4	9	PTA3	LCD_P2 6	LCD_P2 6	PTA3	—	—	—	—	—	LCD_P2 6
5	10	PTA4/ LLWU_P 15	NMI_b	LCD_P2 7	PTA4/ LLWU_P 15	—	—	—	—	LCD_P2 7	NMI_b
6	11	PTA5	LCD_P2 8	LCD_P2 8	PTA5	CMP0_ OUT	—	—	—	—	LCD_P2 8
7	12	PTA6/ LLWU_P 14	LCD_P2 9	LCD_P2 9	PTA6/ LLWU_P 14	XBAR_I N0	—	—	—	—	LCD_P2 9
8	13	PTA7	LCD_P3 0	LCD_P3 0	PTA7	XBAR_O UT0	—	—	—	—	LCD_P3 0
—	14	PTJ0	LCD_P4 8	LCD_P4 8	PTJ0	I2C1_SD A	—	—	—	—	LCD_P4 8
—	15	PTJ1	LCD_P4 9	LCD_P4 9	PTJ1	I2C1_SC L	—	—	—	—	LCD_P4 9
9	16	PTB0	LCD_P3 1	LCD_P3 1	PTB0	—	—	—	—	—	LCD_P3 1
—	17	PTJ2	LCD_P5 0	LCD_P5 0	PTJ2	—	—	—	—	—	LCD_P5 0
10	18	VDD	VDD	VDD	—	—	—	—	—	—	—
11	19	VSS	VSS	VSS	—	—	—	—	—	—	—
12	20	PTB1/ LLWU_P 17	LCD_P3 2	LCD_P3 2	PTB1/ LLWU_P 17	—	—	—	—	—	LCD_P3 2
13	21	PTB2	LCD_P3 3	LCD_P3 3	PTB2	SPI2_P CS0	—	—	—	—	LCD_P3 3
14	22	PTB3	LCD_P3 4	LCD_P3 4	PTB3	SPI2_S CK	—	—	—	—	LCD_P3 4
15	23	PTB4	LCD_P3 5	LCD_P3 5	PTB4	SPI2_MI SO	—	—	—	—	LCD_P3 5
16	24	PTB5	LCD_P3 6	LCD_P3 6	PTB5	SPI2_M OSI	—	—	—	—	LCD_P3 6

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAULT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
17	25	PTB6	LCD_P3 7/ CMP1_I N0	LCD_P3 7/ CMP1_I N0	PTB6	—	—	—	—	—	LCD_P3 7
18	26	PTB7	LCD_P3 8	LCD_P3 8	PTB7	AFE_CL K	—	—	—	—	LCD_P3 8
19	27	PTC0	LCD_P3 9	LCD_P3 9	PTC0	UART3_ RTS_b	XBAR_I N1	PDB0_E XTRG	—	—	LCD_P3 9
20	28	PTC1	LCD_P4 0/ CMP1_I N1	LCD_P4 0/ CMP1_I N1	PTC1	UART3_ CTS_b	—	—	—	—	LCD_P4 0
21	29	PTC2	LCD_P4 1	LCD_P4 1	PTC2	UART3_ TX	XBAR_O UT1	—	—	—	LCD_P4 1
22	30	PTC3/ LLWU_P 13	LCD_P4 2/ CMP0_I N3	LCD_P4 2/ CMP0_I N3	PTC3/ LLWU_P 13	UART3_ RX	—	—	—	—	LCD_P4 2
23	31	PTC4	LCD_P4 3	LCD_P4 3	PTC4	—	—	—	—	—	LCD_P4 3
24	32	VBAT	VBAT	VBAT	—	—	—	—	—	—	—
25	33	XTAL32	XTAL32	XTAL32	—	—	—	—	—	—	—
26	34	EXTAL3 2	EXTAL3 2	EXTAL3 2	—	—	—	—	—	—	—
—	35	NC	NC	NC	—	—	—	—	—	—	—
—	36	NC	NC	NC	—	—	—	—	—	—	—
—	37	NC	NC	NC	—	—	—	—	—	—	—
—	38	NC	NC	NC	—	—	—	—	—	—	—
27	39	VSS	VSS	VSS	—	—	—	—	—	—	—
28	40	TAMPE R2	TAMPE R2	TAMPE R2	—	—	—	—	—	—	—
29	41	TAMPE R1	TAMPE R1	TAMPE R1	—	—	—	—	—	—	—
30	42	TAMPE R0	TAMPE R0	TAMPE R0	—	—	—	—	—	—	—
31	43	AFE_VD DA	AFE_VD DA	AFE_VD DA	—	—	—	—	—	—	—
32	44	AFE_VS SA	AFE_VS SA	AFE_VS SA	—	—	—	—	—	—	—
33	45	AFE_SD ADP0	AFE_SD ADP0	AFE_SD ADP0	—	—	—	—	—	—	—
34	46	AFE_SD ADM0	AFE_SD ADM0	AFE_SD ADM0	—	—	—	—	—	—	—

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAULT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
35	47	AFE_SD ADP1	AFE_SD ADP1	AFE_SD ADP1	—	—	—	—	—	—	—
36	48	AFE_SD ADM1	AFE_SD ADM1	AFE_SD ADM1	—	—	—	—	—	—	—
37	49	VREFH	VREFH	VREFH	—	—	—	—	—	—	—
38	50	VREFL	VREFL	VREFL	—	—	—	—	—	—	—
39	51	AFE_SD ADP2/ CMP1_I N2	AFE_SD ADP2/ CMP1_I N2	AFE_SD ADP2/ CMP1_I N2	—	—	—	—	—	—	—
40	52	AFE_SD ADM2/ CMP1_I N3	AFE_SD ADM2/ CMP1_I N3	AFE_SD ADM2/ CMP1_I N3	—	—	—	—	—	—	—
41	53	VREF	VREF	VREF	—	—	—	—	—	—	—
42	54	AFE_SD ADP3/ CMP1_I N4	AFE_SD ADP3/ CMP1_I N4	AFE_SD ADP3/ CMP1_I N4	—	—	—	—	—	—	—
43	55	AFE_SD ADM3/ CMP1_I N5	AFE_SD ADM3/ CMP1_I N5	AFE_SD ADM3/ CMP1_I N5	—	—	—	—	—	—	—
—	56	NC	NC	NC	—	—	—	—	—	—	—
—	57	NC	NC	NC	—	—	—	—	—	—	—
44	58	PTC5/ LLWU_P 12	ADC0_S E0/ CMP2_I N0	ADC0_S E0/ CMP2_I N0	PTC5/ LLWU_P 12	UART0_ RTS_b	—	LPTMR1 _ALT1	—	—	—
45	59	PTC6	ADC0_S E1/ CMP2_I N1	ADC0_S E1/ CMP2_I N1	PTC6	UART0_ CTS_b	QTMR0_ TMR1	PDB0_E XTRG	—	—	—
46	60	PTC7	ADC0_S E2/ CMP2_I N2	ADC0_S E2/ CMP2_I N2	PTC7	UART0_ TX	XBAR_O UT2	—	—	—	—
47	61	PTD0/ LLWU_P 11	CMP0_I N0	CMP0_I N0	PTD0/ LLWU_P 11	UART0_ RX	XBAR_I N2	—	—	—	—
—	62	PTJ3	DISABL ED	—	PTJ3	LPUART 0_RTS_ b	CMP2_ OUT	—	—	—	—
—	63	PTJ4	DISABL ED	—	PTJ4	LPUART 0_CTS_ b	LPTMR1 _ALT1	—	—	—	—

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAULT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
48	64	PTD1	DISABLED	—	PTD1	UART1_TX	SPI0_PCS0	XBAR_OUT3	QTMR0_TMR3	—	—
49	65	PTD2/LLWU_P10	CMP0_IN1	CMP0_IN1	PTD2/LLWU_P10	UART1_RX	SPI0_SCK	XBAR_IN3	—	—	—
—	66	PTJ5	DISABLED	—	PTJ5	LPUART0_TX	—	—	—	—	—
—	67	PTJ6/LLWU_P18	DISABLED	—	PTJ6/LLWU_P18	LPUART0_RX	—	—	—	—	—
—	68	PTJ7	DISABLED	—	PTJ7	LPTMR1_ALT2	—	—	—	—	—
50	69	PTD3	DISABLED	—	PTD3	UART1_CTS_b	SPI0_MOSI	LPTMR1_ALT2	—	—	—
—	70	PTK0	ADC0_SE12	ADC0_SE12	PTK0	LPTMR1_ALT3	—	—	—	—	—
—	71	NC	NC	NC	—	—	—	—	—	—	—
—	72	NC	NC	NC	—	—	—	—	—	—	—
—	73	NC	NC	NC	—	—	—	—	—	—	—
—	74	NC	NC	NC	—	—	—	—	—	—	—
—	75	PTK1	ADC0_SE13	ADC0_SE13	PTK1	—	—	—	—	—	—
51	76	PTD4/LLWU_P9	ADC0_SE3	ADC0_SE3	PTD4/LLWU_P9	UART1_RTS_b	SPI0_MISO	LPTMR1_ALT3	—	—	—
52	77	PTD5	ADC0_SE4a	ADC0_SE4a	PTD5	LPTMR0_ALT3	QTMR0_TMR0	UART3_CTS_b	—	—	—
53	78	PTD6/LLWU_P8	ADC0_SE5a	ADC0_SE5a	PTD6/LLWU_P8	LPTMR0_ALT2	CMP1_OUT	UART3_RTS_b	—	—	—
54	79	PTD7/LLWU_P7	CMP0_IN4	CMP0_IN4	PTD7/LLWU_P7	I2C0_SCL	XBAR_IN4	UART3_RX	—	—	—
55	80	PTE0	DISABLED	—	PTE0	I2C0_SDA	XBAR_OUT4	UART3_TX	CLKOUT	—	—
—	81	PTK2	ADC0_SE14	ADC0_SE14	PTK2	UART0_TX	—	—	—	—	—
—	82	PTK3/LLWU_P19	ADC0_SE15	ADC0_SE15	PTK3/LLWU_P19	UART0_RX	—	—	—	—	—
56	83	PTE1	RESET_b	—	PTE1	—	—	—	—	—	RESET_b
57	84	PTE2	EXTAL	EXTAL	PTE2	EWM_IN	XBAR_IN6	I2C1_SDA	—	—	—

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAULT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
58	85	PTE3	XTAL	XTAL	PTE3	EWM_UT_b	AFE_CLK	I2C1_SCL	—	—	—
59	86	VSS	VSS	VSS	—	—	—	—	—	—	—
60	87	VSSA	VSSA	VSSA	—	—	—	—	—	—	—
61	88	VDDA	VDDA	VDDA	—	—	—	—	—	—	—
62	89	VDD	VDD	VDD	—	—	—	—	—	—	—
63	90	PTE4	DISABLED	—	PTE4	LPTMR0_ALT1	UART2_CTS_b	EWM_IN	—	—	—
64	91	PTE5/LLWU_P6	DISABLED	—	PTE5/LLWU_P6	QTMR0_TMR3	UART2_RTS_b	EWM_UT_b	—	—	—
65	92	PTE6/LLWU_P5	SWD_DIO	CMP0_IN2	PTE6/LLWU_P5	XBAR_IN5	UART2_RX	—	I2C0_SCL	—	SWD_DIO
66	93	PTE7	SWD_CLK	ADC0_SE6a	PTE7	XBAR_OUT5	UART2_TX	—	I2C0_SDA	—	SWD_CLK
67	94	PTF0/LLWU_P4	ADC0_SE7a/CMP2_IN3	ADC0_SE7a/CMP2_IN3	PTF0/LLWU_P4	RTC_CLKOUT	QTMR0_TMR2	CMP0_OUT	—	—	—
68	95	PTF1	LCD_P0/ADC0_SE8/CMP2_IN4	LCD_P0/ADC0_SE8/CMP2_IN4	PTF1	QTMR0_TMR0	XBAR_OUT6	—	—	—	LCD_P0
69	96	PTF2	LCD_P1/ADC0_SE9/CMP2_IN5	LCD_P1/ADC0_SE9/CMP2_IN5	PTF2	CMP1_OUT	RTC_CLKOUT	—	—	—	LCD_P1
—	97	PTK4	LCD_P51	LCD_P51	PTK4	XBAR_IN9	AFE_CLK	—	—	—	LCD_P51
—	98	PTK5	DISABLED	—	PTK5	UART1_RX	—	—	—	—	—
—	99	PTK6	DISABLED	—	PTK6	UART1_TX	—	—	—	—	—
70	100	PTF3/LLWU_P20	LCD_P2	LCD_P2	PTF3/LLWU_P20	SPI1_PCS0	LPTMR0_ALT2	UART0_RX	—	—	LCD_P2
71	101	PTF4	LCD_P3	LCD_P3	PTF4	SPI1_SCK	LPTMR0_ALT1	UART0_TX	—	—	LCD_P3
72	102	PTF5	LCD_P4	LCD_P4	PTF5	SPI1_MISO	I2C1_SCL	—	—	—	LCD_P4

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAU LT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
73	103	PTF6/ LLWU_P 3	LCD_P5	LCD_P5	PTF6/ LLWU_P 3	SPI1_M OSI	I2C1_SD A	—	—	—	LCD_P5
74	104	PTF7	LCD_P6	LCD_P6	PTF7	QTMR0_ TMR2	CLKOUT	CMP2_ OUT	—	—	LCD_P6
—	105	PTK7	LCD_P5 2	LCD_P5 2	PTK7	I2C0_SC L	XBAR_O UT9	—	—	—	LCD_P5 2
—	106	PTL0	LCD_P5 3	LCD_P5 3	PTL0	I2C0_SD A	—	—	—	—	LCD_P5 3
—	107	NC	NC	NC	—	—	—	—	—	—	—
—	108	NC	NC	NC	—	—	—	—	—	—	—
—	109	NC	NC	NC	—	—	—	—	—	—	—
75	110	PTG0	LCD_P7	LCD_P7	PTG0	QTMR0_ TMR1	LPTMR0_ ALT3	—	—	—	LCD_P7
76	111	PTG1/ LLWU_P 2	LCD_P8/ ADC0_S E10	LCD_P8/ ADC0_S E10	PTG1/ LLWU_P 2	—	LPTMR0_ ALT1	—	—	—	LCD_P8
77	112	PTG2/ LLWU_P 1	LCD_P9/ ADC0_S E11	LCD_P9/ ADC0_S E11	PTG2/ LLWU_P 1	SPI0_P CS0	—	—	—	—	LCD_P9
78	113	PTG3	LCD_P1 0	LCD_P1 0	PTG3	SPI0_S CK	I2C0_SC L	—	—	—	LCD_P1 0
79	114	PTG4	LCD_P1 1	LCD_P1 1	PTG4	SPI0_M OSI	I2C0_SD A	—	—	—	LCD_P1 1
80	115	PTG5	LCD_P1 2	LCD_P1 2	PTG5	SPI0_MI SO	LPTMR0_ ALT2	—	—	—	LCD_P1 2
81	116	PTG6/ LLWU_P 0	LCD_P1 3	LCD_P1 3	PTG6/ LLWU_P 0	—	LPTMR0_ ALT3	—	—	—	LCD_P1 3
82	117	PTG7	LCD_P1 4	LCD_P1 4	PTG7	—	LPTMR1_ ALT1	—	—	—	LCD_P1 4
83	118	PTH0	LCD_P1 5	LCD_P1 5	PTH0	LPUART 0_CTS_ b	—	—	—	—	LCD_P1 5
84	119	PTH1	LCD_P1 6	LCD_P1 6	PTH1	LPUART 0_RTS_ b	—	—	—	—	LCD_P1 6
85	120	PTH2	LCD_P1 7	LCD_P1 7	PTH2	LPUART 0_RX	—	—	—	—	LCD_P1 7
86	121	PTH3	LCD_P1 8	LCD_P1 8	PTH3	LPUART 0_TX	—	—	—	—	LCD_P1 8
87	122	PTH4	LCD_P1 9	LCD_P1 9	PTH4	—	LPTMR1_ ALT2	—	—	—	LCD_P1 9

Table continues on the next page...

Table 39. Signal Multiplexing and Pin Assignments (continued)

100 LQFP	144 LQFP	Pin Name	DEFAULT	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
88	123	PTH5	LCD_P2_0	LCD_P2_0	PTH5	—	LPTMR1_ALT3	—	—	—	LCD_P2_0
89	124	PTH6	DISABLED	—	PTH6	UART1_CTS_b	SPI1_PCS0	XBAR_IN7	—	—	—
90	125	PTH7	DISABLED	—	PTH7	UART1_RTS_b	SPI1_SCK	XBAR_OUT7	—	—	—
91	126	PTI0/LLWU_P21	CMP0_IN5	CMP0_IN5	PTI0/LLWU_P21	UART1_RX	XBAR_IN8	SPI1_MISO	SPI1_MOSI	—	—
92	127	PTI1	DISABLED	—	PTI1	UART1_TX	XBAR_OUT8	SPI1_MOSI	SPI1_MISO	—	—
—	128	PTL1	LCD_P5_4	LCD_P5_4	PTL1	XBAR_IN10	—	—	—	—	LCD_P5_4
—	129	PTL2	LCD_P5_5	LCD_P5_5	PTL2	XBAR_OUT10	—	—	—	—	LCD_P5_5
93	130	PTI2/LLWU_P22	LCD_P2_1	LCD_P2_1	PTI2/LLWU_P22	LPUART0_RX	—	—	—	—	LCD_P2_1
94	131	PTI3	LCD_P2_2	LCD_P2_2	PTI3	LPUART0_TX	CMP2_OUT	—	—	—	LCD_P2_2
95	132	VSS	VSS	VSS	—	—	—	—	—	—	—
—	133	VDD	VDD	VDD	—	—	—	—	—	—	—
96	134	VLL3	VLL3	VLL3	—	—	—	—	—	—	—
97	135	VLL2	VLL2/LCD_P6_0	VLL2/LCD_P6_0	PTM0	—	—	—	—	—	LCD_P6_0
98	136	VLL1	VLL1/LCD_P6_1	VLL1/LCD_P6_1	PTM1	—	—	—	—	—	LCD_P6_1
99	137	VCAP2	VCAP2/LCD_P6_2	VCAP2/LCD_P6_2	PTM2	—	—	—	—	—	LCD_P6_2
100	138	VCAP1	VCAP1/LCD_P6_3	VCAP1/LCD_P6_3	PTM3	—	—	—	—	—	LCD_P6_3
—	139	PTL3	LCD_P5_6	LCD_P5_6	PTL3	EWM_IN	—	—	—	—	LCD_P5_6
—	140	PTL4	LCD_P5_7	LCD_P5_7	PTL4	EWM_OUT_b	—	—	—	—	LCD_P5_7
—	141	PTL5/LLWU_P23	LCD_P5_8	LCD_P5_8	PTL5/LLWU_P23	—	—	—	—	—	LCD_P5_8
—	142	PTL6	LCD_P5_9	LCD_P5_9	PTL6	—	—	—	—	—	LCD_P5_9

5.2 KM35 Pinouts

5.2.1 100-pin LQFP

The following figure represents the KM35 100 LQFP pinouts.

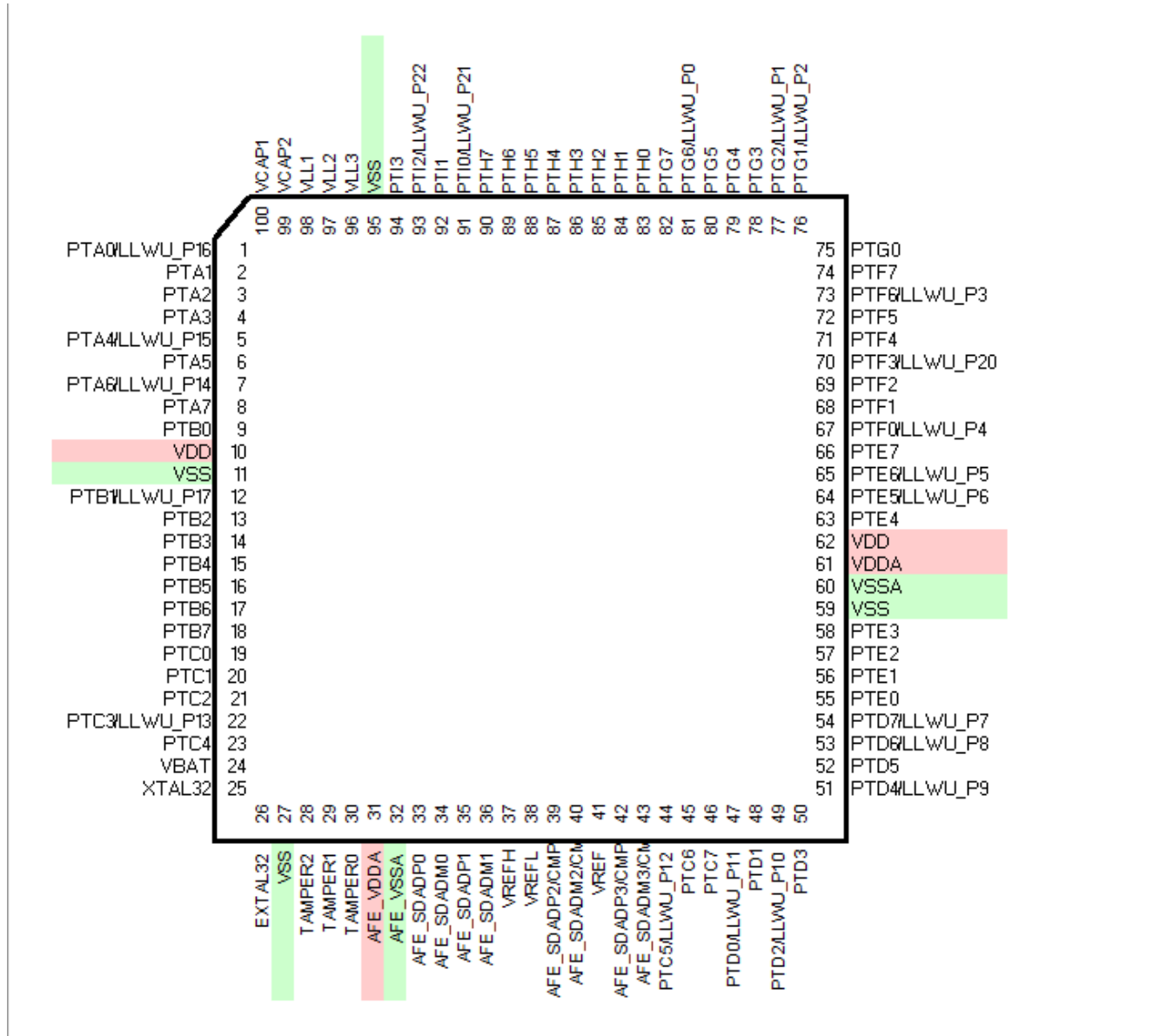


Figure 11. 100-pin LQFP Pinout Diagram

5.2.2 144-pin LQFP

The following figure represents the KM35 144 LQFP pinouts:

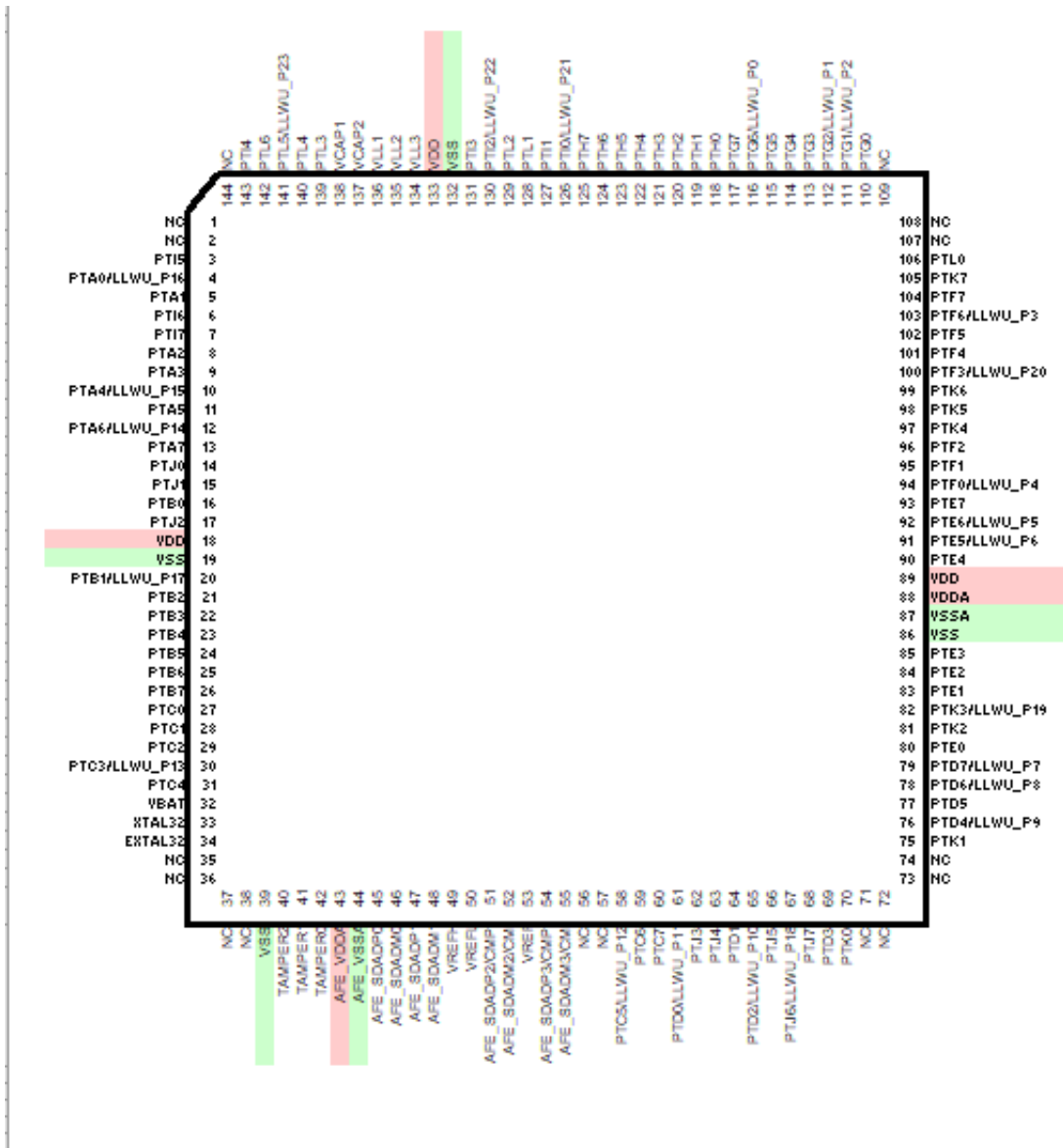


Figure 12. 144-pin LQFP Pinout Diagram

6 Ordering parts

6.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to nxp.com and perform a part number search for the following device numbers:

- MKM35Z256VLL7
- MKM35Z256VLQ7
- MKM35Z512VLL7
- MKM35Z512VLQ7

7 Part identification

7.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

7.2 Format

Part numbers for this device have the following format:

Q KM## A FFF R T PP CC N

7.3 Fields

Following table lists the possible values for each field in the part number (not all combinations are valid):

Field	Description	Values
Q	Qualification status	<ul style="list-style-type: none"> • M = Fully qualified, general market flow • P = Pre-qualification
KM##	Kinetis family	<ul style="list-style-type: none"> • KM35
A	Key attribute	<ul style="list-style-type: none"> • Z = Cortex[®]-M0+
FFF	Program flash memory size	<ul style="list-style-type: none"> • 256 = 256 KB • 512 = 512 KB
R	Silicon revision	<ul style="list-style-type: none"> • (Blank) = Main • A = Revision after main

Table continues on the next page...

Field	Description	Values
T	Temperature range (°C)	<ul style="list-style-type: none"> V = -40 to 105
PP	Package identifier	<ul style="list-style-type: none"> LL = 100 LQFP (14 mm x 14 mm) LQ = 144 LQFP (20 mm x 20 mm)
CC	Maximum CPU frequency (MHz)	<ul style="list-style-type: none"> 7 = 75 MHz
N	Packaging type	<ul style="list-style-type: none"> R = Tape and reel (Blank) = Trays

7.4 Example

This is an example part number:

- MKM35Z512VLL7

8 Terminology and guidelines

8.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

8.1.1 Example

This is an example of an operating requirement:

Symbol	Description	Min.	Max.	Unit
V _{DD}	1.0 V core supply voltage	0.9	1.1	V

8.2 Definition: Operating behavior

Unless otherwise specified, an *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

8.2.1 Example

This is an example of an operating behavior:

Symbol	Description	Min.	Max.	Unit
I_{WP}	Digital I/O weak pullup/pulldown current	10	130	μA

8.3 Definition: Attribute

An *attribute* is a specified value or range of values for a technical characteristic that are guaranteed, regardless of whether you meet the operating requirements.

8.3.1 Example

This is an example of an attribute:

Symbol	Description	Min.	Max.	Unit
CIN_D	Input capacitance: digital pins	—	7	pF

8.4 Definition: Rating

A *rating* is a minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:

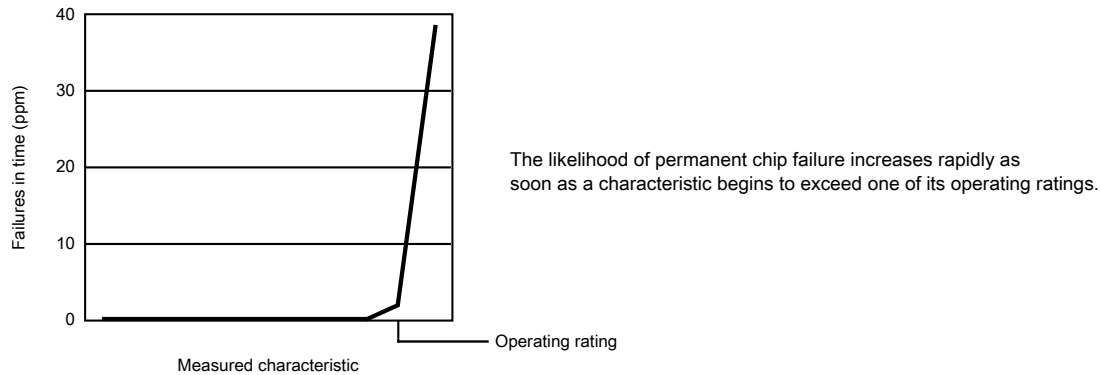
- *Operating ratings* apply during operation of the chip.
- *Handling ratings* apply when the chip is not powered.

8.4.1 Example

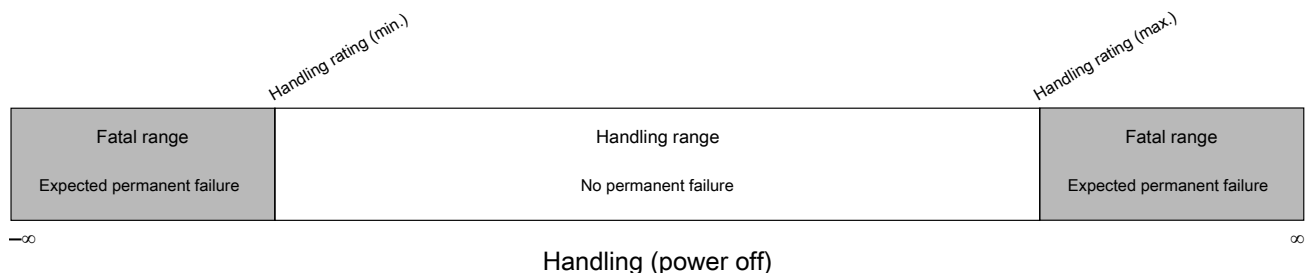
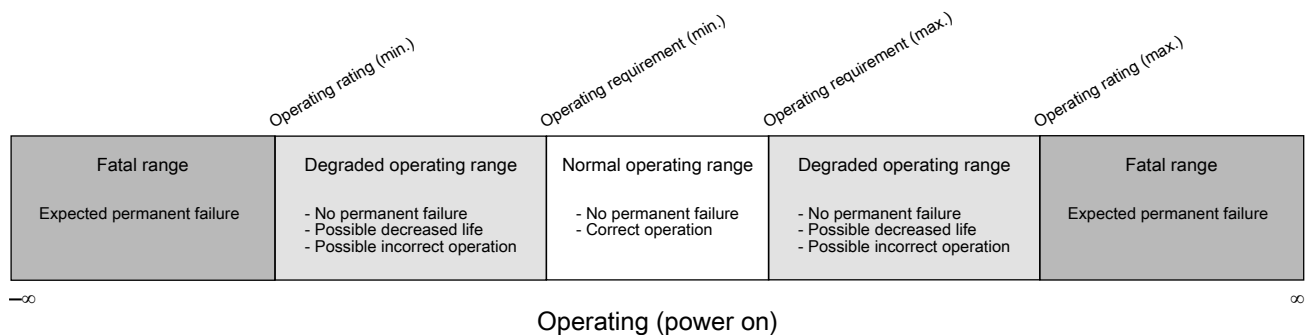
This is an example of an operating rating:

Symbol	Description	Min.	Max.	Unit
V _{DD}	1.0 V core supply voltage	-0.3	1.2	V

8.5 Result of exceeding a rating



8.6 Relationship between ratings and operating requirements



8.7 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

Terminology and guidelines

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

8.8 Definition: Typical value

A *typical value* is a specified value for a technical characteristic that:

- Lies within the range of values specified by the operating behavior
- Given the typical manufacturing process, is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions

Typical values are provided as design guidelines and are neither tested nor guaranteed.

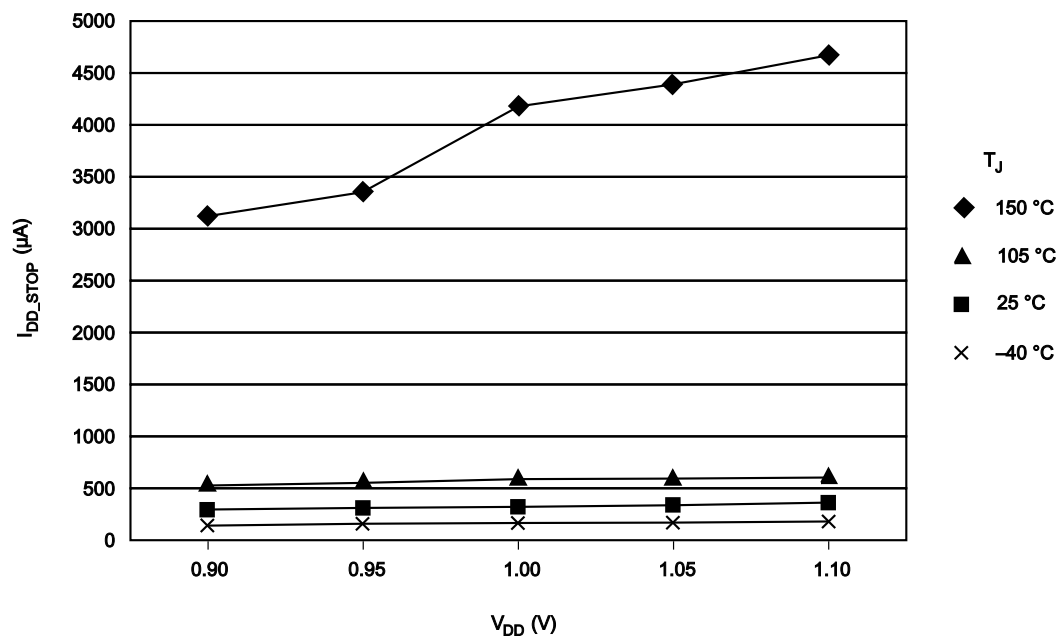
8.8.1 Example 1

This is an example of an operating behavior that includes a typical value:

Symbol	Description	Min.	Typ.	Max.	Unit
I_{WP}	Digital I/O weak pullup/pulldown current	10	70	130	μA

8.8.2 Example 2

This is an example of a chart that shows typical values for various voltage and temperature conditions:



8.9 Typical value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Symbol	Description	Value	Unit
T _A	Ambient temperature	25	°C
V _{DD}	3.3 V supply voltage	3.3	V

9 Revision History

The following table provides a revision history for this document.

Table 40. Revision History

Rev. No.	Date	Substantial Changes
Rev.0	08/2019	Initial release
Rev.1	12/2019	<ul style="list-style-type: none"> Updated the footnotes of ESD handling ratings Updated Thermal Attributes Removed EzPort column from KM35 Signal Multiplexing and Pin Assignments

Table continues on the next page...

Revision History

Table 40. Revision History (continued)

Rev. No.	Date	Substantial Changes
Rev.2	03/2020	<ul style="list-style-type: none">• ADdedd IDD values in Power consumption operating behaviors• EDitorial updates• Updated Low power features in Front Matter

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